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浙江杭可精密仪器有限公司
Zhejiang Hangke Precision Instrument Co., Ltd.
杭州市萧山区鸿达路157号
NO.157 HONGDA ROAD, XIAOSHAN, HANGZHOU, ZHEJIANG.

SOCKET TEST
burn-in

Precision
Instrument



PITCH
DEVICE

BALL
LAND
ARRAY

MAXIMUM
VOLTAGE

BOARD

MEMORY
TEST

SOCKET

RANG

CONTACT
RESISTANCE

TYPE

SERIES

APPLICABLE

Burn-in

ATiS®

Simulation
Count

SOLUTION

INSERTION

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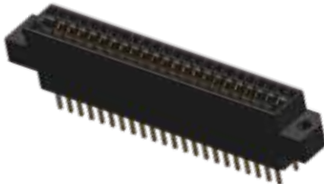
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COMPANY PROFILE 企业简介

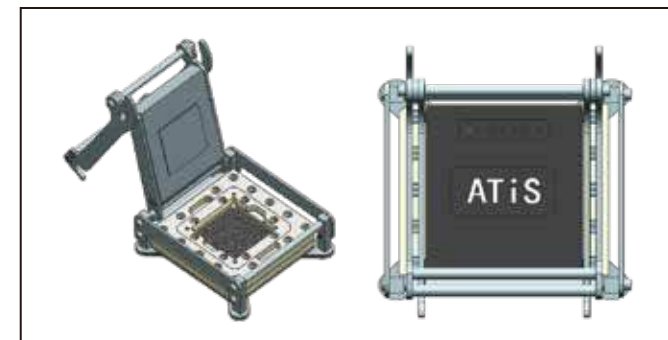
浙江杭可精密仪器有限公司，是浙江杭可仪器有限公司的全资子公司，独立于2023年3月7日，总部设立于浙江省杭州市萧山区，前身是浙江杭可仪器有限公司第四研究所。公司成立后专注于设计、生产各类老化座、测试座、连接器和探针产品，并具有金属模具和塑胶模具设计生产能力，配备了日本SODICK线割机、精密数控加工中心、磨床、德国ARBURG及日本住友注塑机等一批先进生产设备。

自创设以来，公司始终紧贴客户需求，坚持独立研发，拥有成熟的销售体系及卓越的售后团队能够快速响应客户需求，产品及服务触达全球，深受众多客户的肯定。

Zhejiang Hangke Precision Instrument Co., Ltd., a wholly-owned subsidiary of Zhejiang Hangke Instrument Co., Ltd., is independent on March 7, 2023, head quartered in Xiaoshan District, Hangzhou City, Zhejiang Province, formerly known as the Fourth Research Institute of Zhejiang Hangke Instrument Co., Ltd. After its establishment, the company focused on the design and production of various burn-in sockets, test sockets, connectors and probe products, and has the design and production capacity of metal molds and plastic molds, and is equipped with a number of advanced production equipment, such as SODICK wire cutting machines, precision CNC machining centers, grinding machines, German ARBURG and Japanese Sumitomo injection molding machines.

Since its establishment, the company has always been close to clients' needs, adhere to independent research and development, has a mature sales system and excellent after-sales team can quickly respond to customer needs, products and services reach the whole world, and are affirmed by many clients.

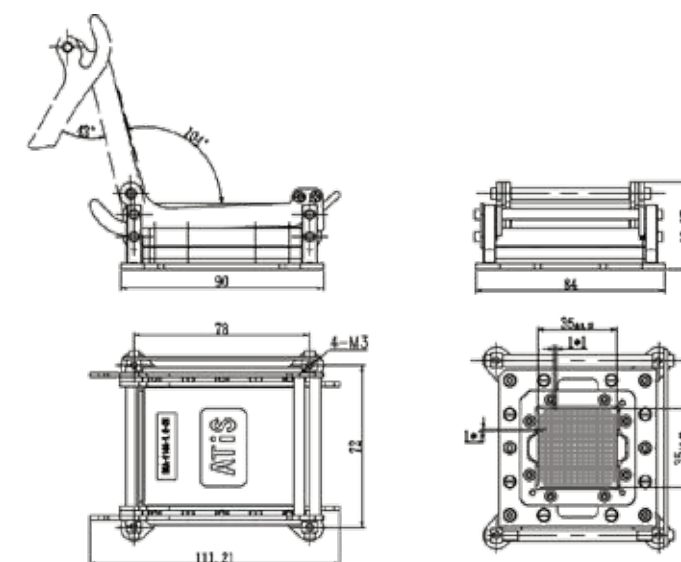
BGA BALL GRID ARRAY



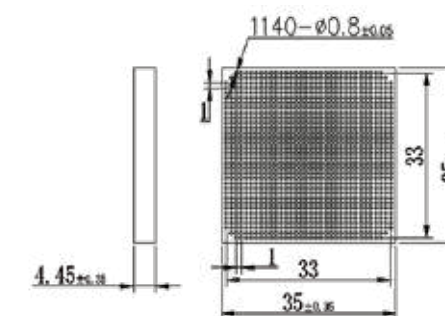
BGA-1144-1.0-01

- 材质/Material
 - 主体/Body: PEEK
 - 接触/Contact: Pogopin
 - 镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
 - 额定电流/Rated Current: 3A
 - 绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
 - 接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
 - 使用温度/Operating Temperature Range: -55°C~+175°C
 - 抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

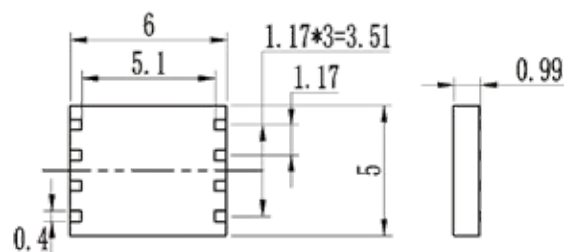
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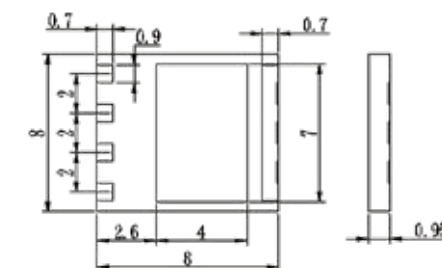
器件封装要求含/Device Packaging Requirements Including



NO-LEAD



NO-LEAD



DFN

DUAL

FLAT

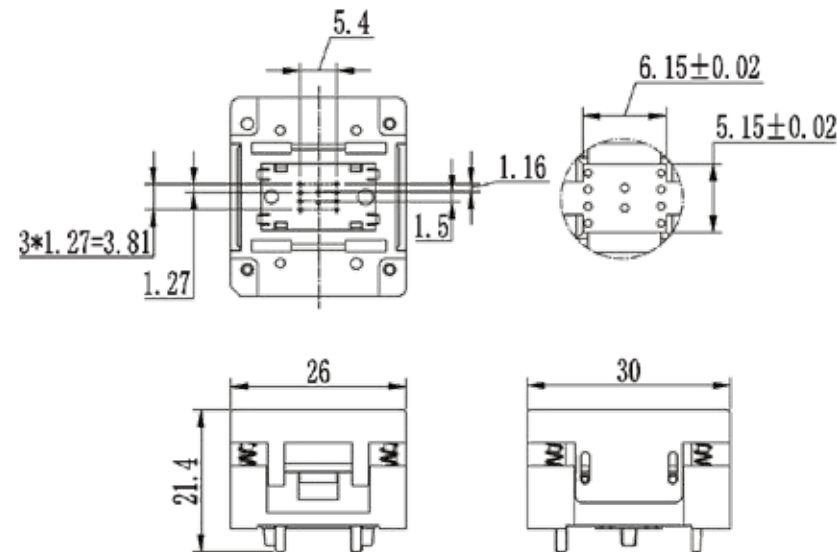
NO-LEAD

DFN-5X6-Z

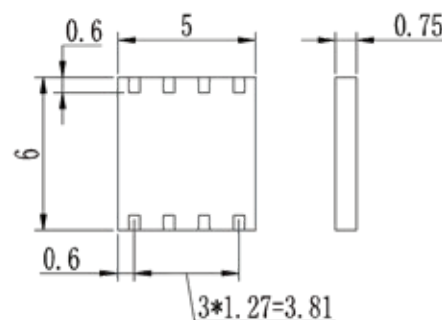


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: pogopin
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



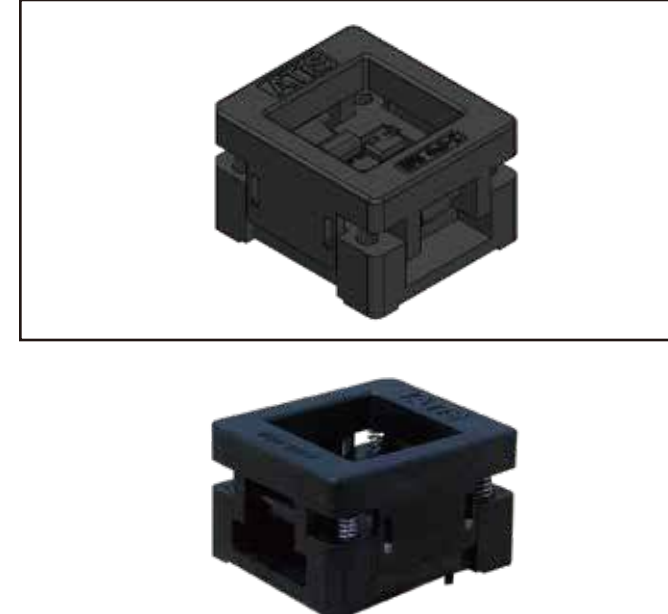
DFN

DUAL

FLAT

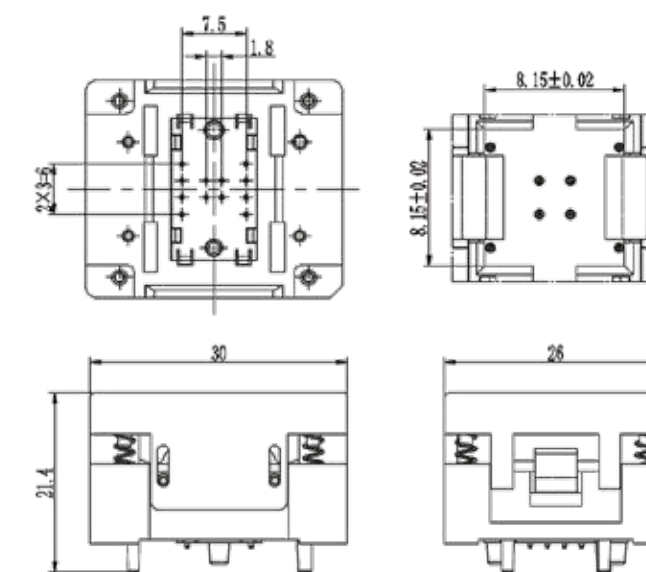
NO-LEAD

DFN-8X8-Z

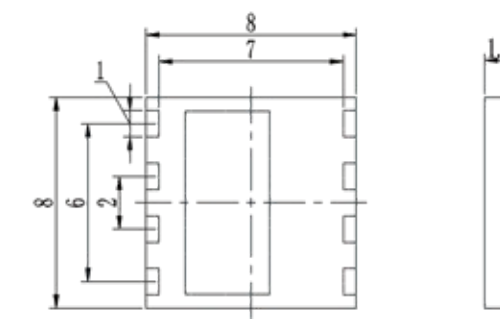


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: pogopin
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



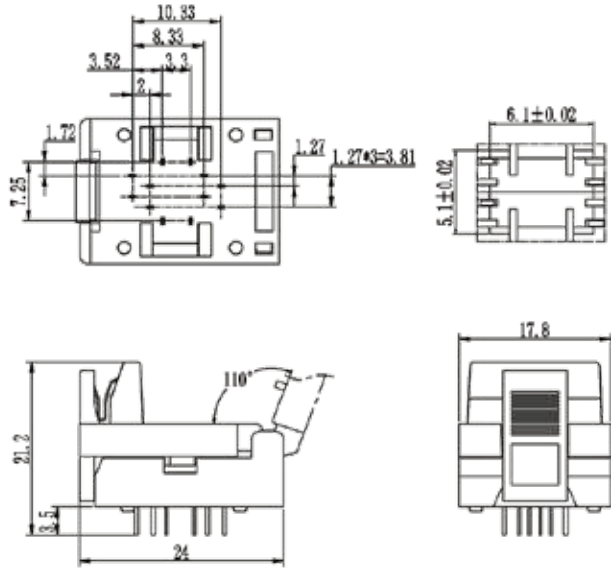
DFN
DUAL
FLAT
NO-LEAD

DFN-5X6-S

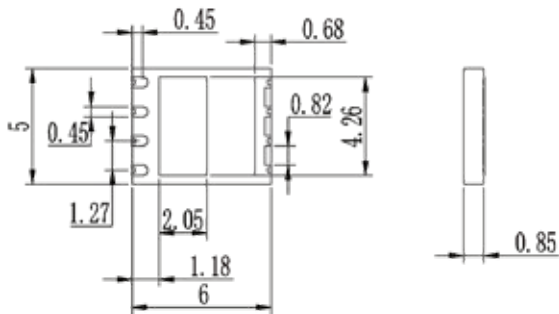


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗 疲 劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



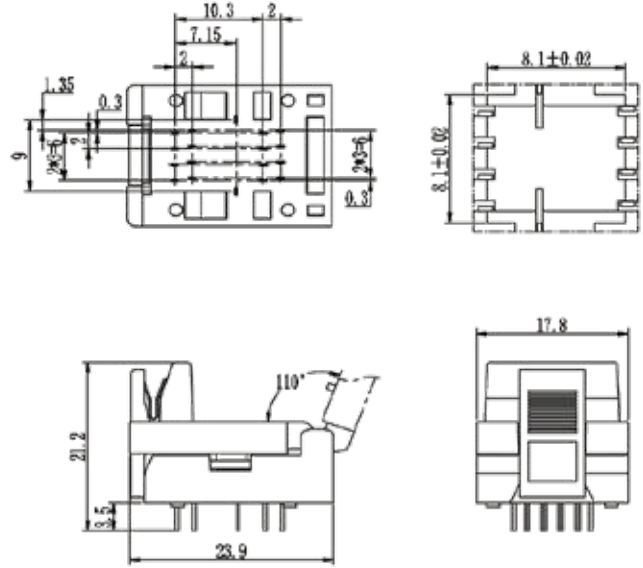
DFN
DUAL
FLAT
NO-LEAD

DFN-8X8-S

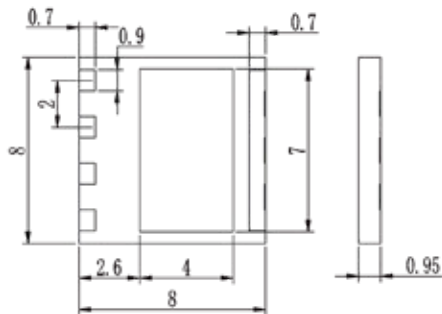


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗 疲 劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



SMD

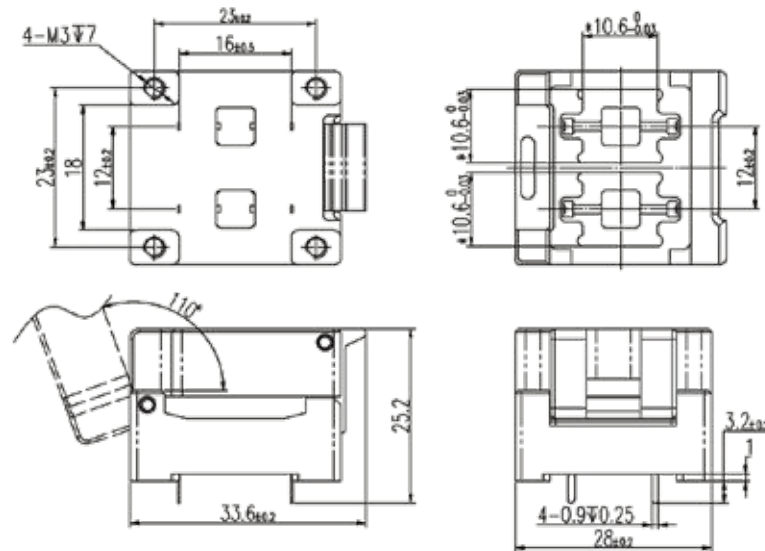
SURFACE MOUNTED DEVICES

SMD-10X10

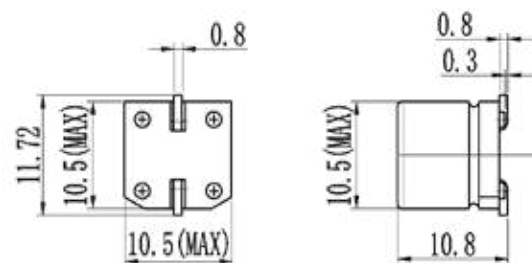


- 材质/Material
主体/Body: PEEK
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 3A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 30mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



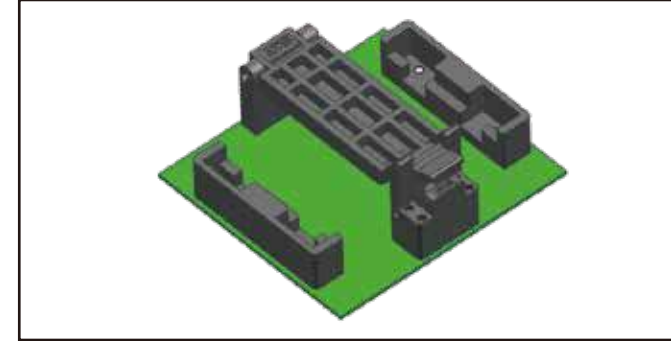
器件封装要求含/Device Packaging Requirements Including



DCM

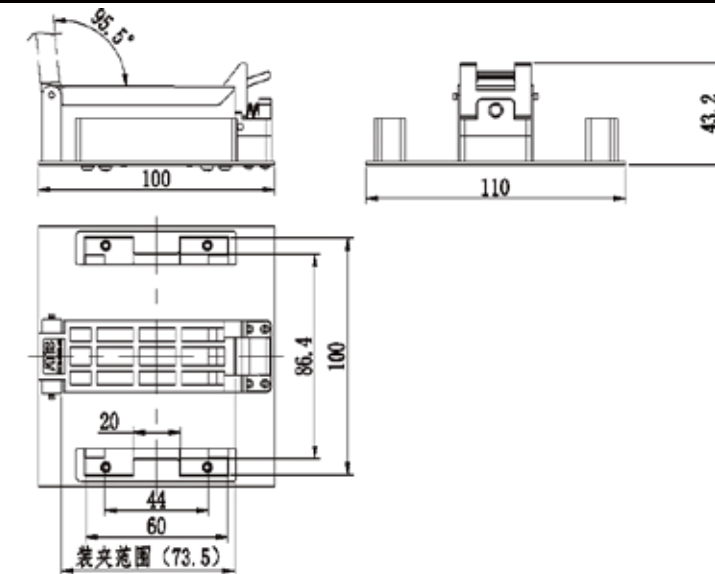
SURFACE MOUNTED DEVICES

DCM-8232-03-X

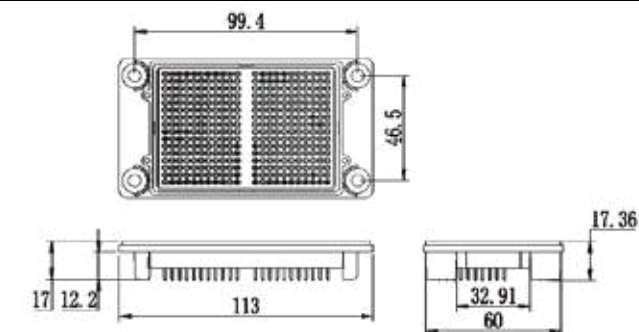


- 材质/Material
主体/Body: PPS+gf30 (Black)
- 电特性/Electrical Characteristics
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

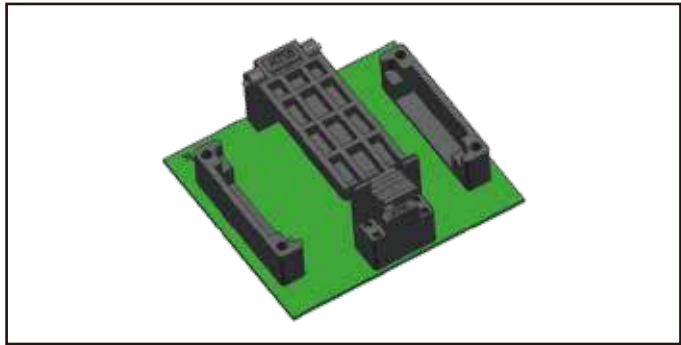
产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

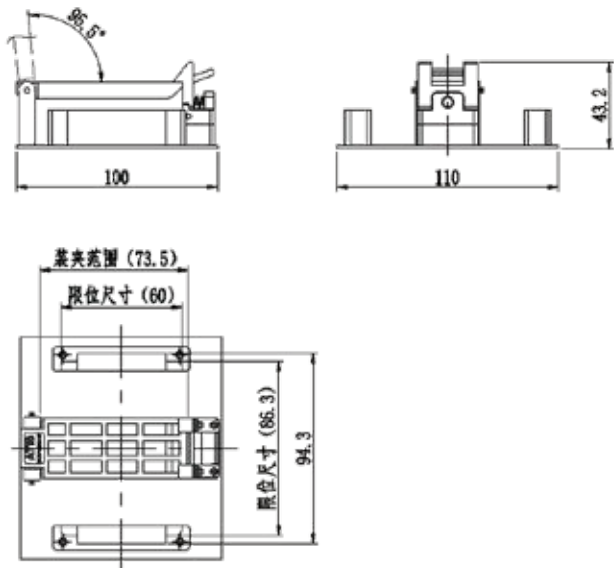


DCM-8232-03-K

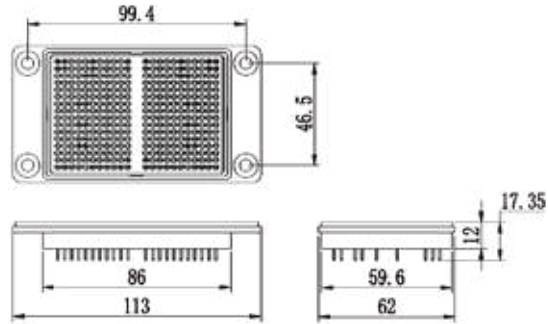


- 材质/Material
主体/Body: PPS+gf30 (Black)
- 电特性/Electrical Characteristics
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

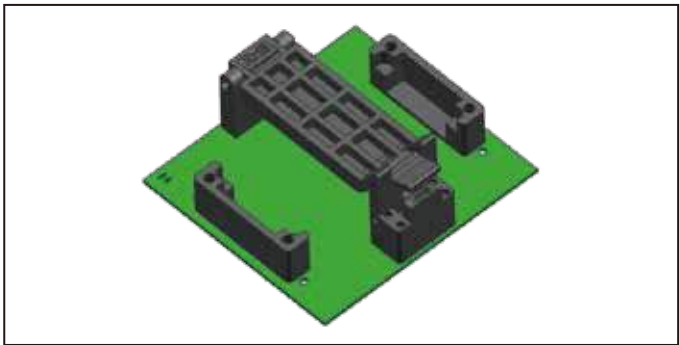
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器件封装要求含/Device Packaging Requirements Including

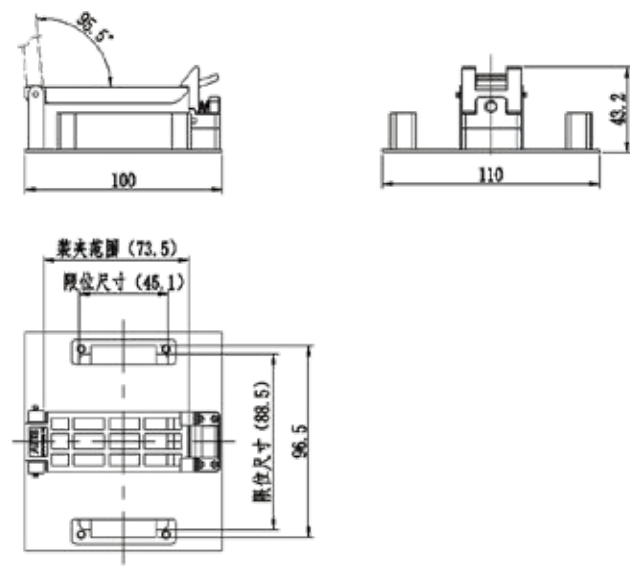


DCM-8232-03-Z

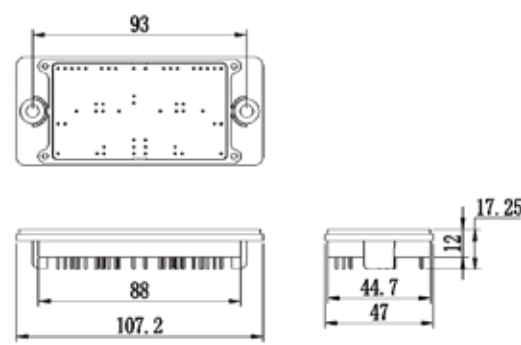


- 材质/Material
主体/Body: PPS+gf30 (Black)
- 电特性/Electrical Characteristics
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

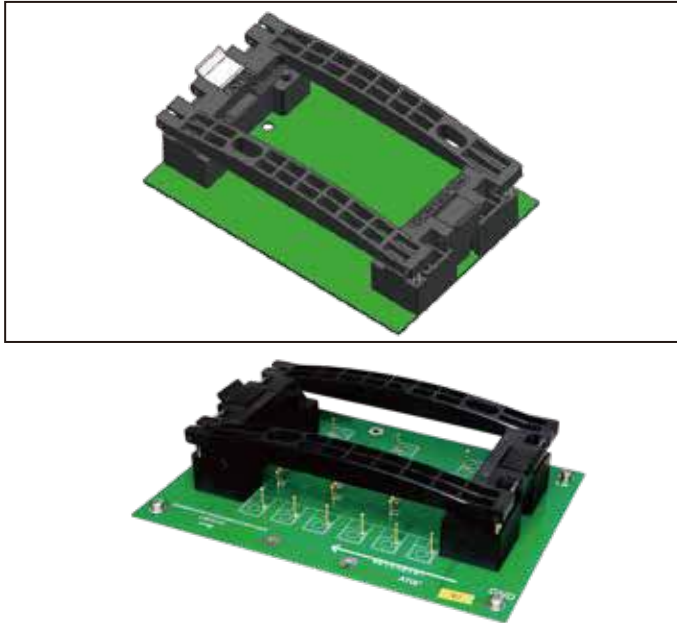
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器件封装要求含/Device Packaging Requirements Including

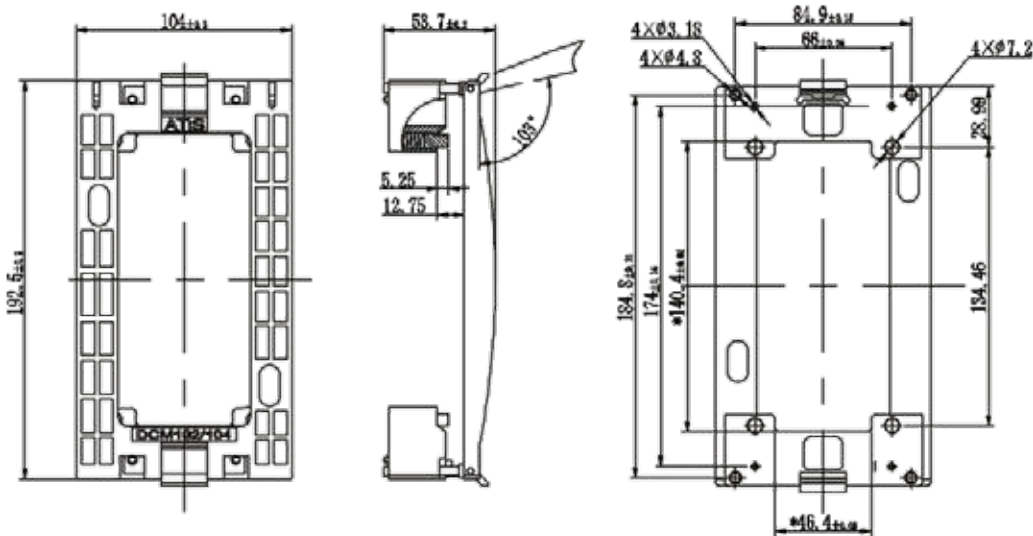


DCM-192/104-S

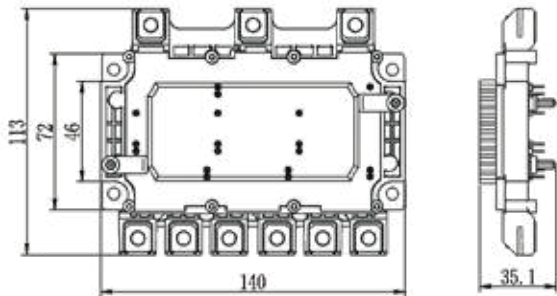


- 材质/Material
主体/Body: PPS+gf30 (Black)
- 电特性/Electrical Characteristics
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

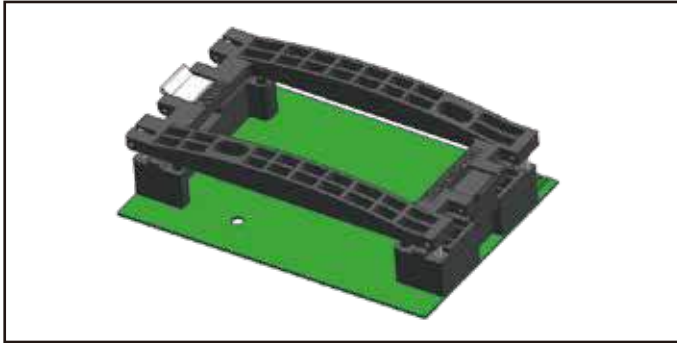
产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

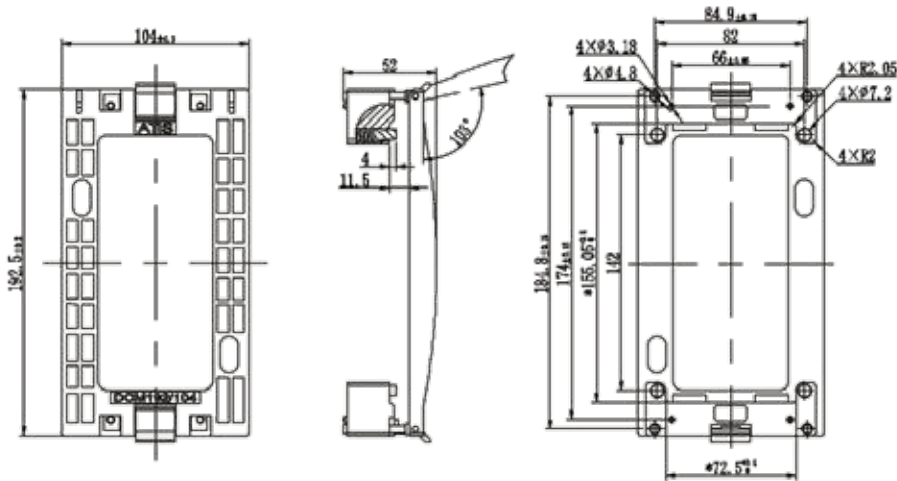


DCM-192/104-M

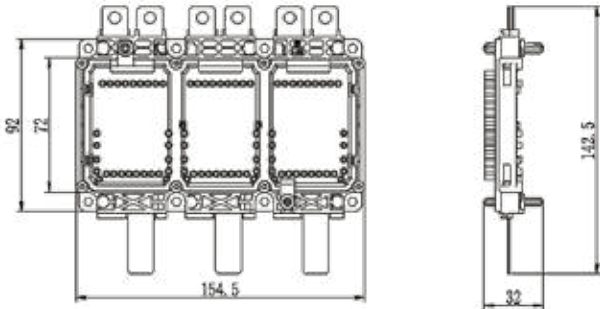


- 材质/Material
主体/Body: PPS+gf30 (Black)
- 电特性/Electrical Characteristics
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

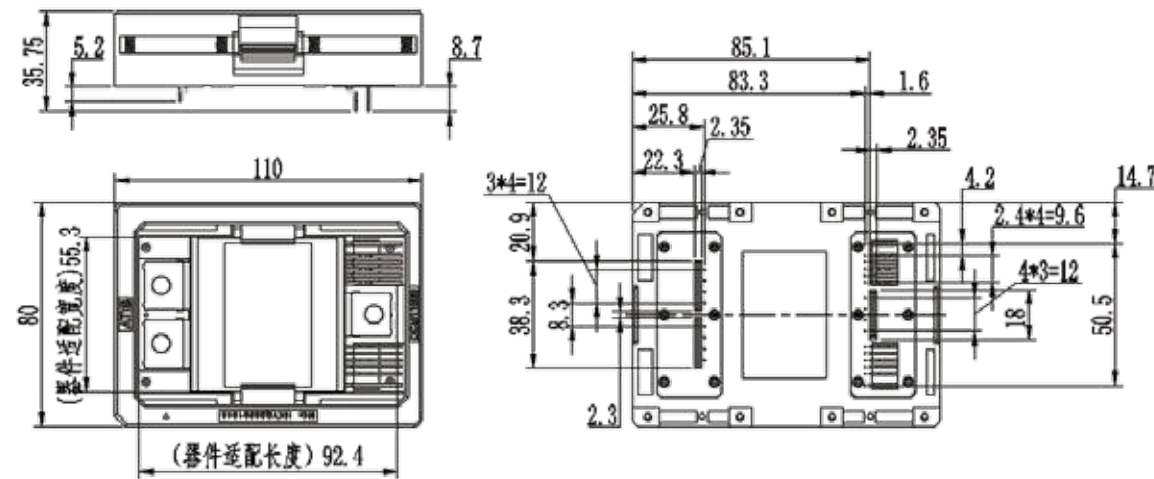


DCM-11080

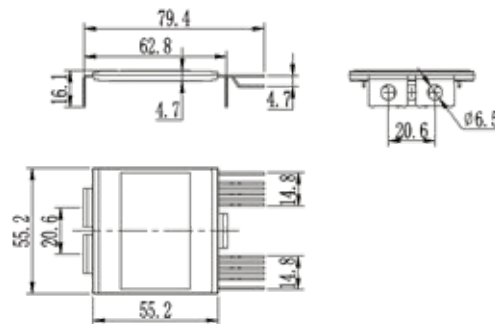


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: pogopin
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

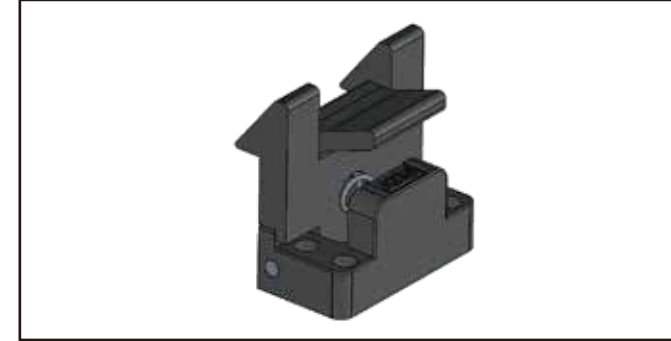
产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

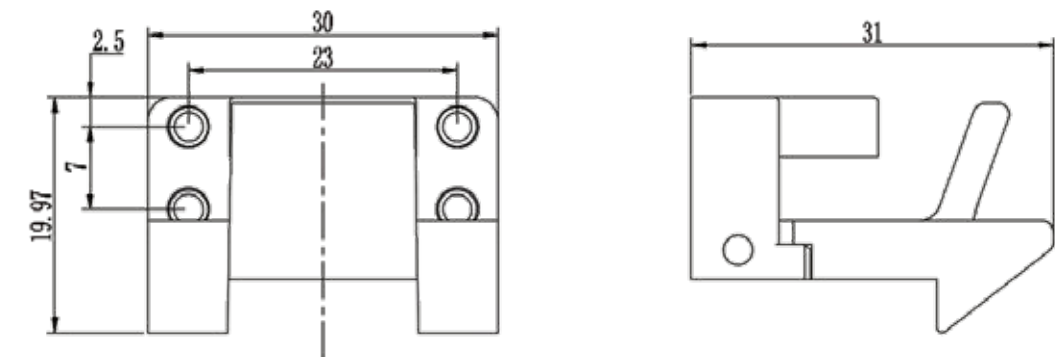


DCM-3021



- 材质/Material
主体/Body: PPS+gf30 (Black)
- 电特性/Electrical Characteristics
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: ≥10000 cycle

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

DCM-8232-02

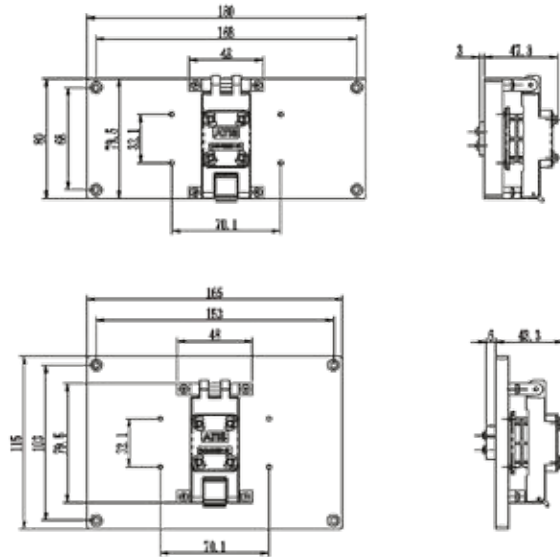


- 材质/Material
主体/Body: PPS+gf30 (Black)

- 电特性/Electrical Characteristics

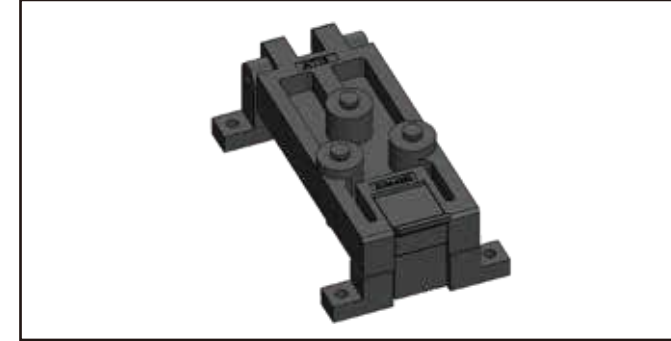
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

DCM-8232

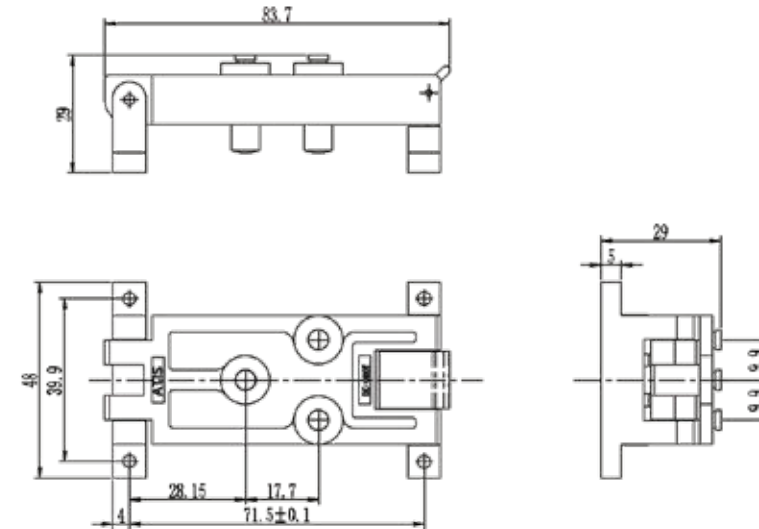


- 材质
主体: PPS+gf30 (Black)

- 电特性/Electrical Characteristics

- 其他
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

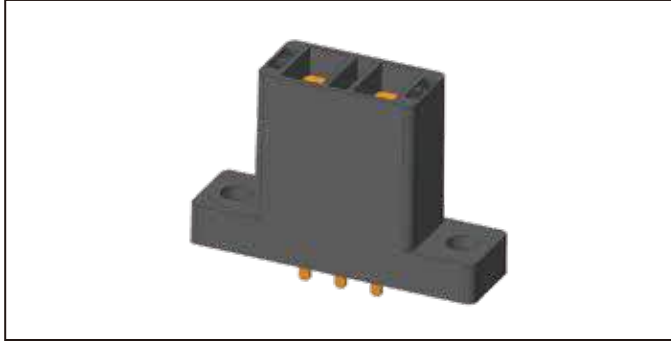
产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

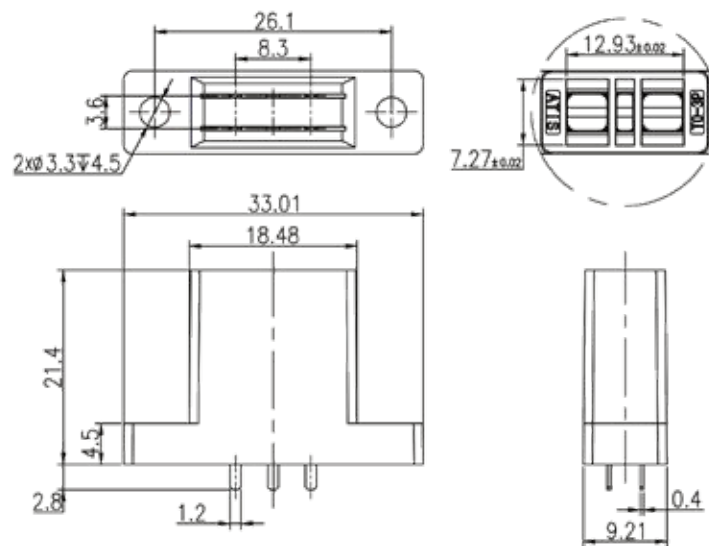
TO TRANSISTOR OUTLINE

TO-3P

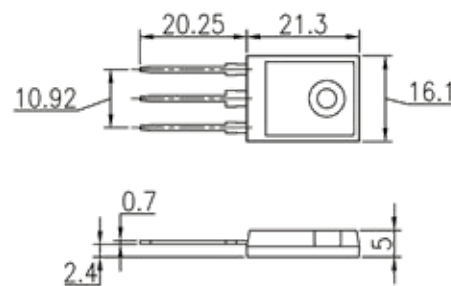


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 10A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

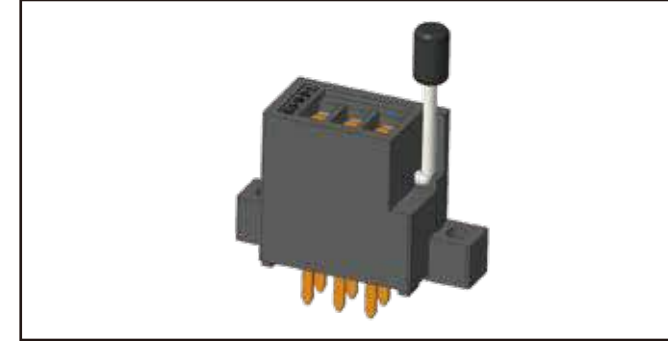


器件封装要求含/Device Packaging Requirements Including



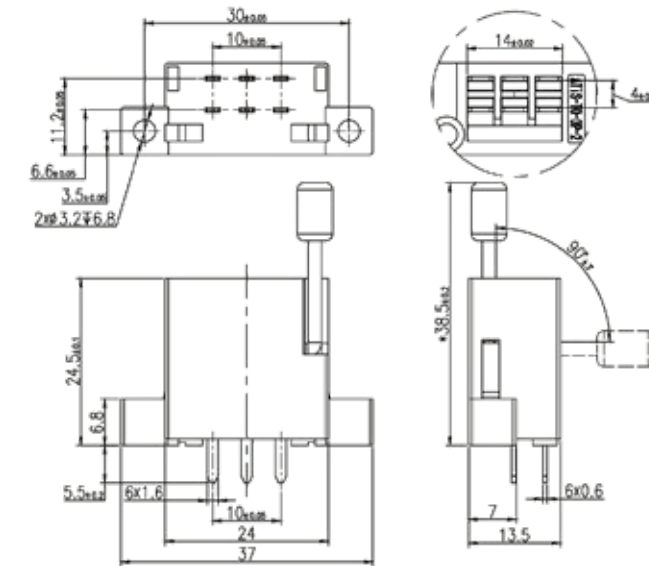
TO TRANSISTOR OUTLINE

TO-3P-02

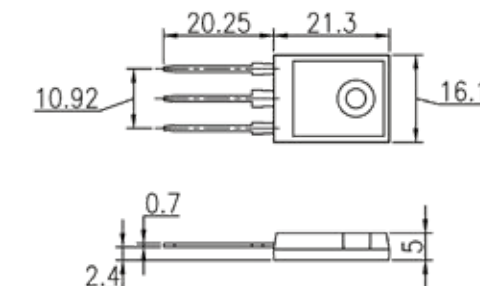


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 80A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

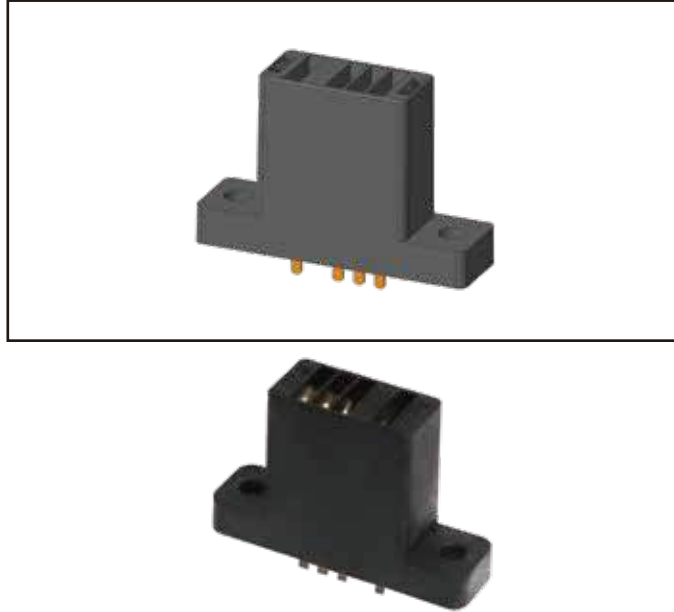


器件封装要求含/Device Packaging Requirements Including



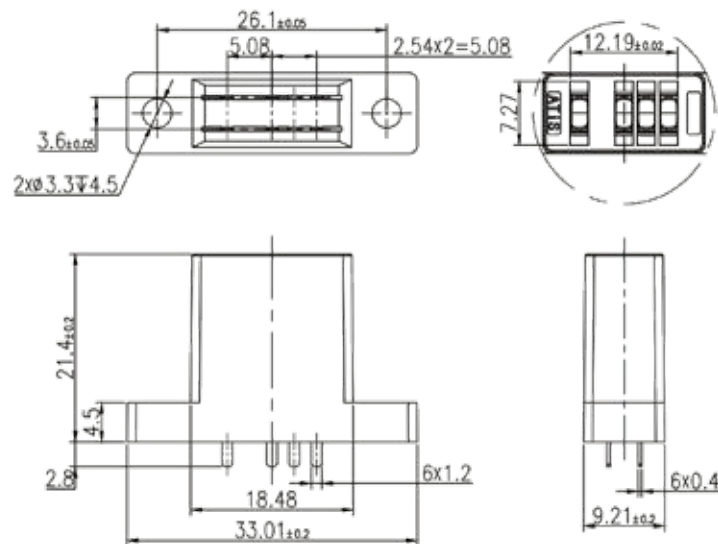
TO TRANSISTOR OUTLINE

TO-4P

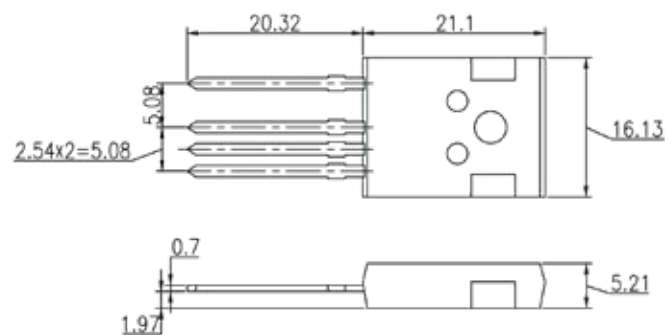


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 10A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

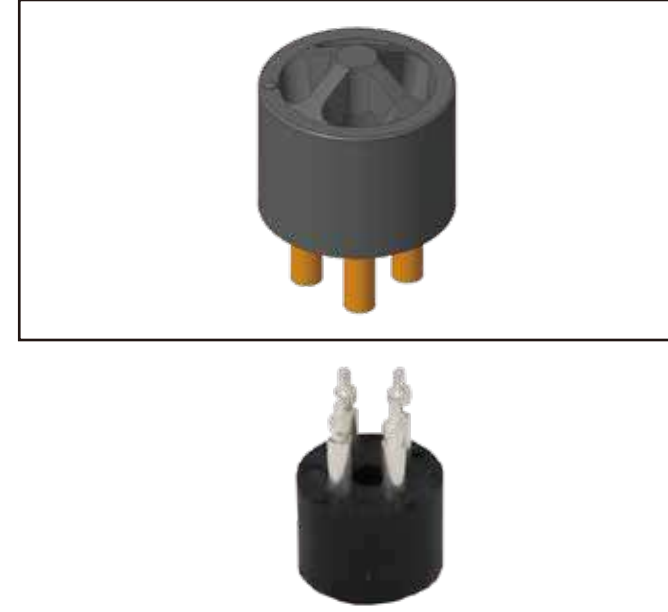


器件封装要求含/Device Packaging Requirements Including



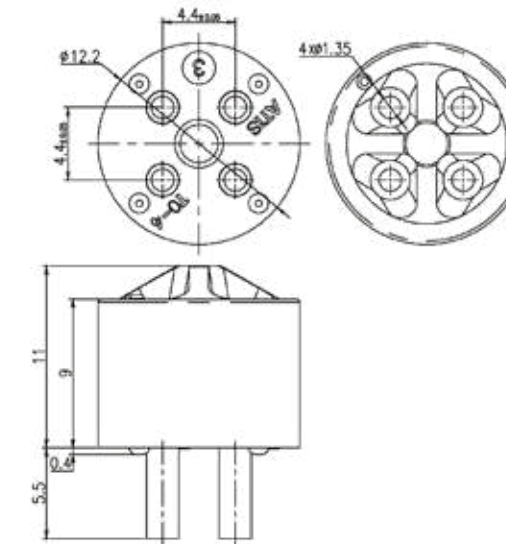
TO TRANSISTOR OUTLINE

TO-4P(B4)

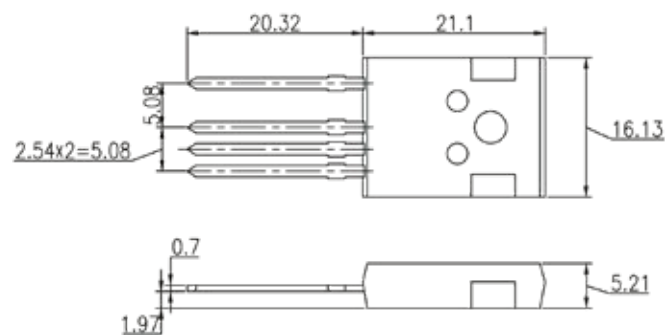


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



TRANSISTOR OUTLINE

[illegible]

Technical drawings of two types of connectors, 1 and 2, showing front and side views with dimensions.

Connector 1:

- Front View:** Dimensions include 20.25 (width of pins), 21.3 (width of body), 10.92 (height of pins), and 16.1 (height of body).
- Side View:** Dimensions include 0.7 (pin thickness), 2.4 (base thickness), and 5 (body thickness).

Connector 2:

- Front View:** Dimensions include 20.32 (width of pins), 21.1 (width of body), 16.13 (height of body), and 2.54x2=5.08 (pin spacing).
- Side View:** Dimensions include 0.7 (pin thickness), 1.97 (base thickness), and 5.21 (body thickness).

TRANSISTOR OUTLINE

Technical drawings of two types of connectors, Type 1 and Type 2, showing front, side, and detail views with dimensions.

Type 1 Connector Dimensions:

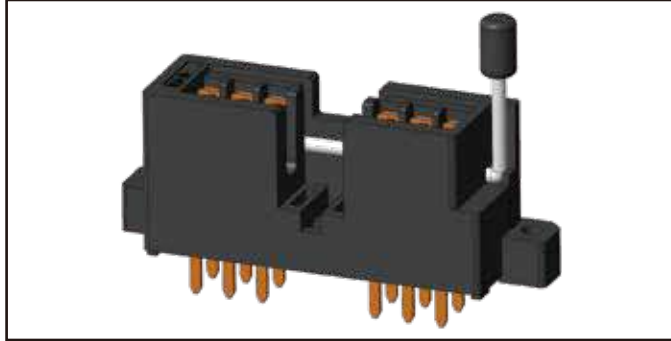
- Front View: Pin spacing 20.25, Pin width 21.3, Pin height 10.92, Pin length 16.1.
- Side View: Pin thickness 0.7, Pin length 2.4.
- Detail View: Pin thickness 0.7, Pin length 2.4.

Type 2 Connector Dimensions:

- Front View: Pin spacing 20.32, Pin width 21.1, Pin height 16.13, Pin length 5.08, Pin thickness 2.54x2=5.08.
- Side View: Pin thickness 0.7, Pin length 1.97.
- Detail View: Pin thickness 0.7, Pin length 1.97.

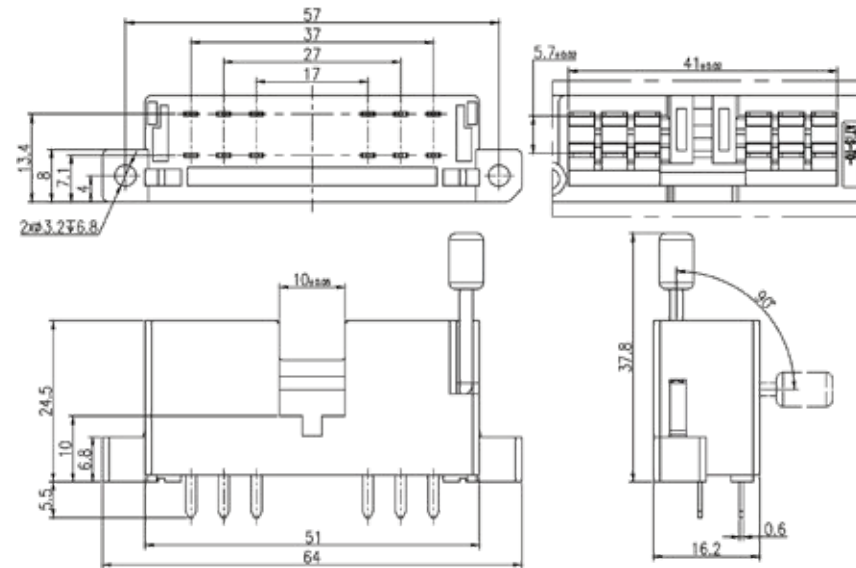
TO TRANSISTOR OUTLINE

TO-6-02

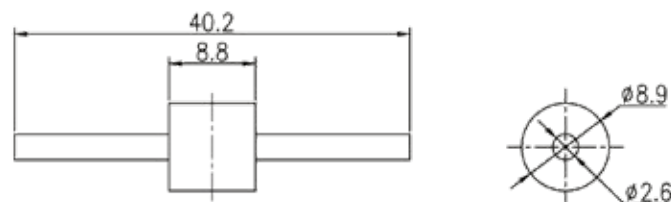


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 50A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
● 使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



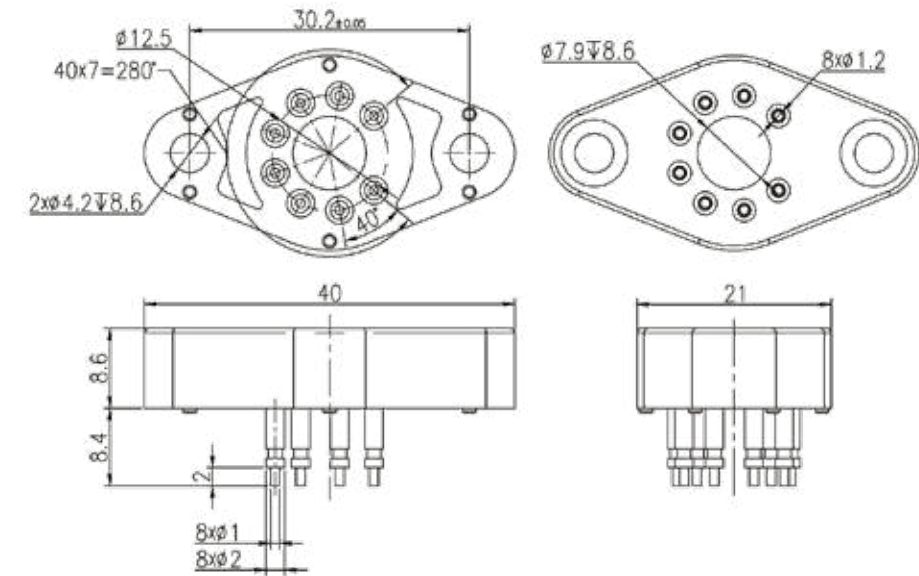
TO TRANSISTOR OUTLINE

TO-8



- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

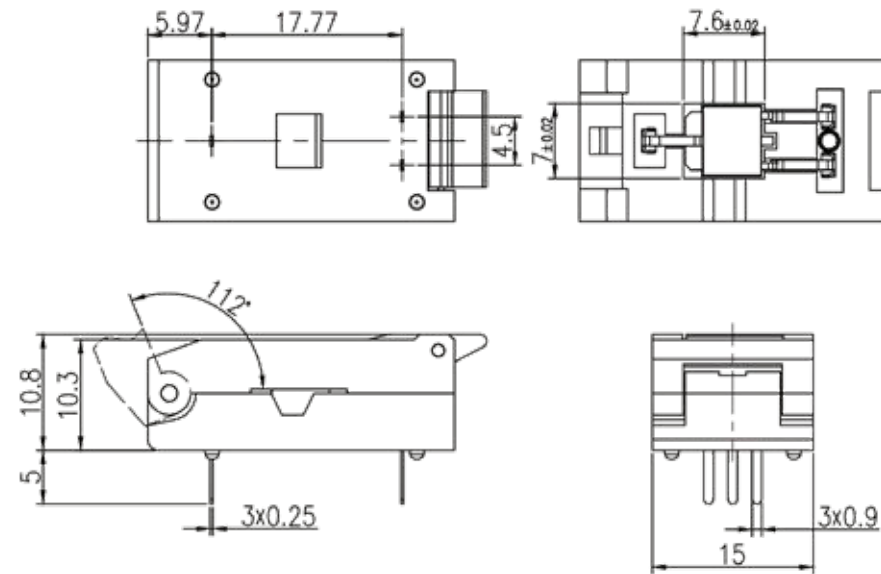
TO TRANSISTOR OUTLINE

TO-252

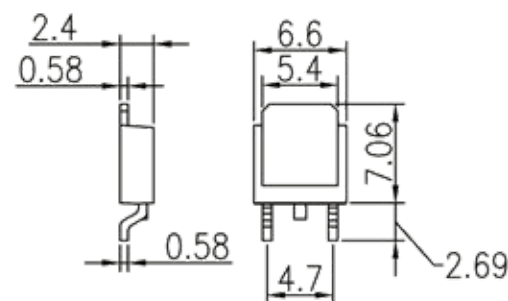


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 3A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



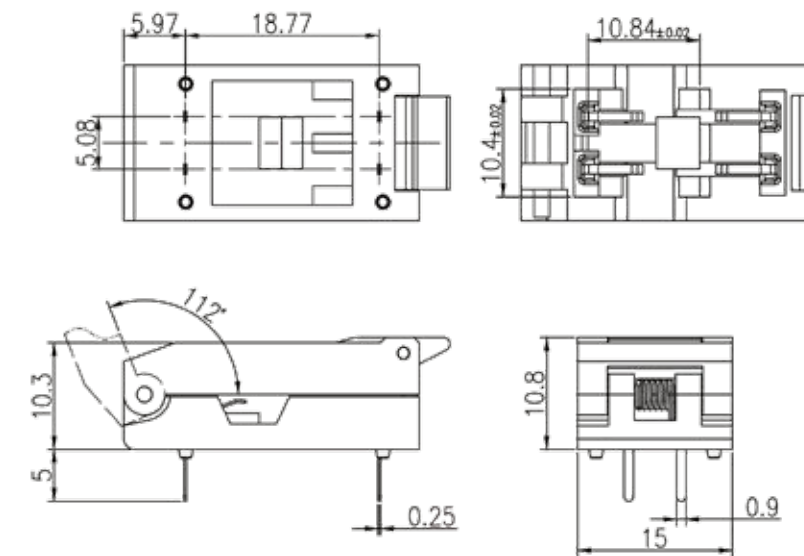
TO TRANSISTOR OUTLINE

TO-263-3L

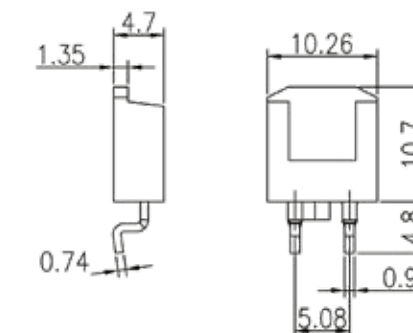


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 3A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



TO

TRANSISTOR

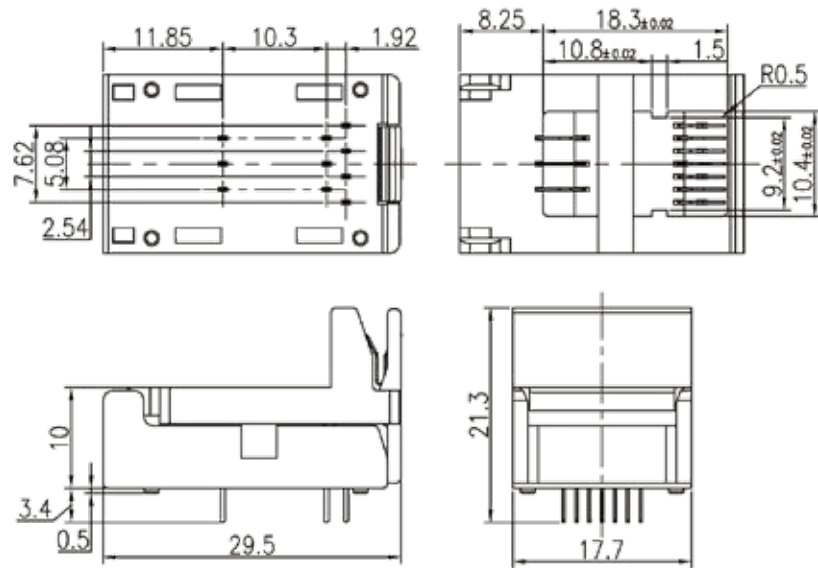
OUTLINE

TO-263-6L

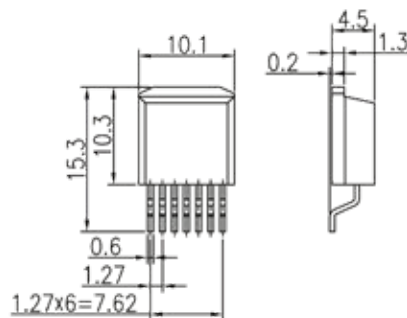


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



TO

TRANSISTOR

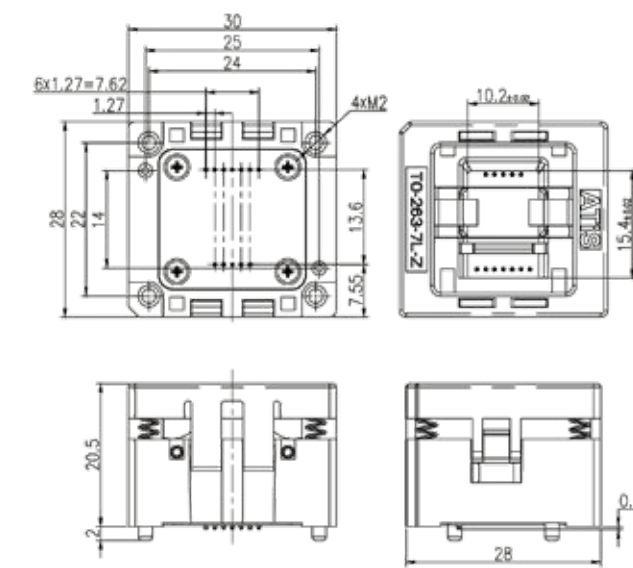
OUTLINE

TO-263-7L-Z

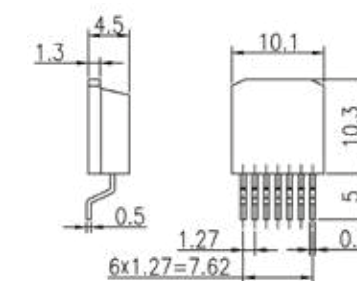


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: pogopin
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



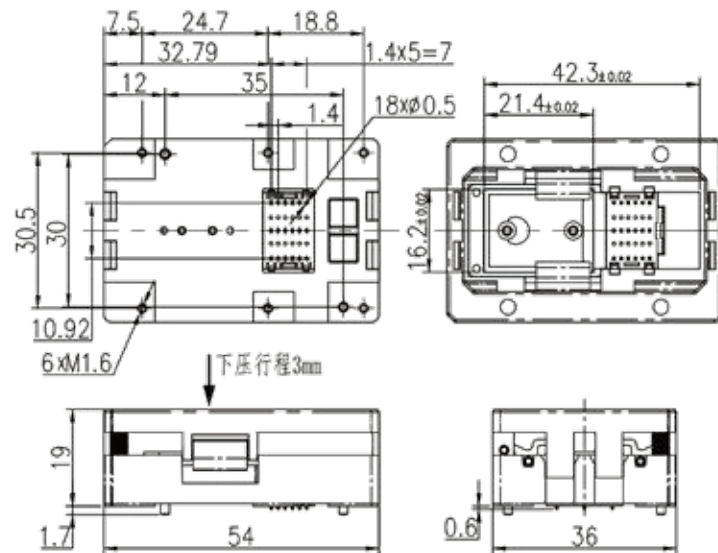
TO TRANSISTOR OUTLINE

TO-247-3L-Z

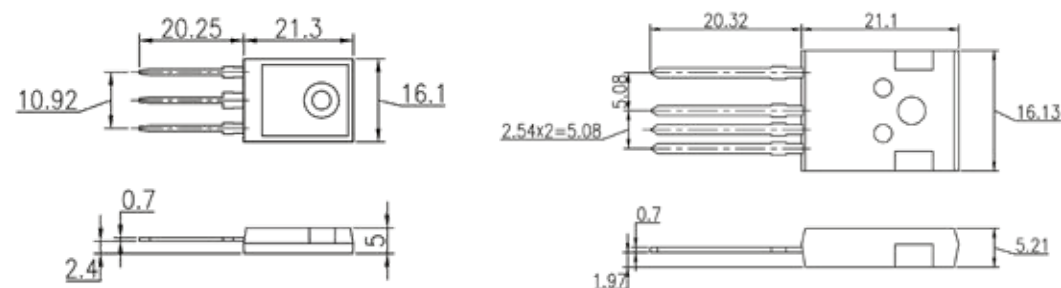


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: pogopin
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



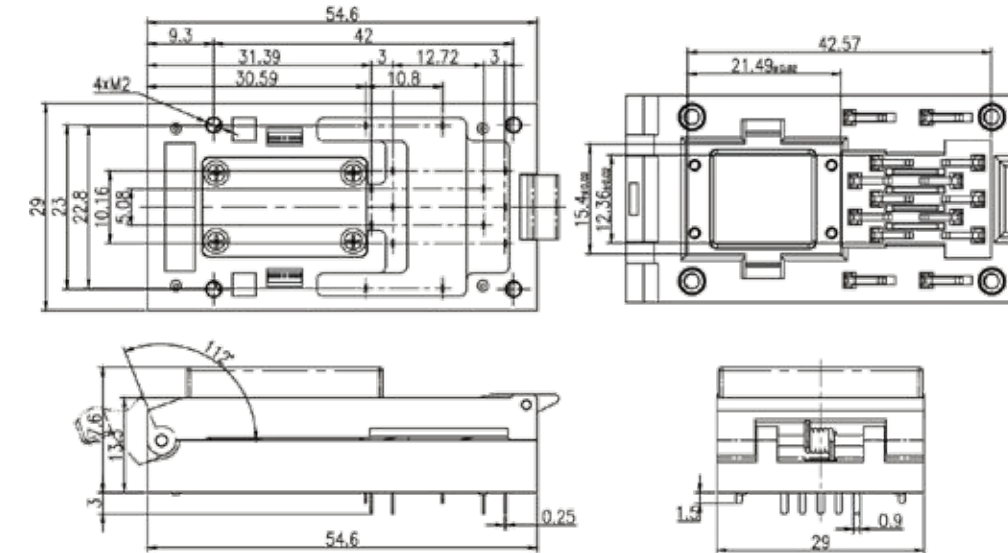
TO TRANSISTOR OUTLINE

TO-247-3LA

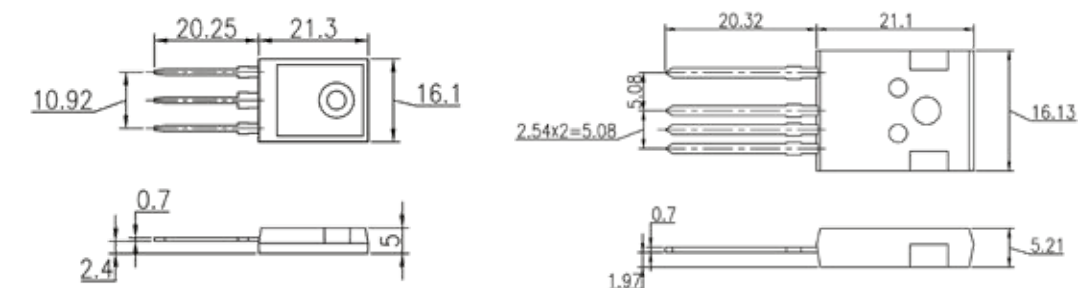


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 3A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



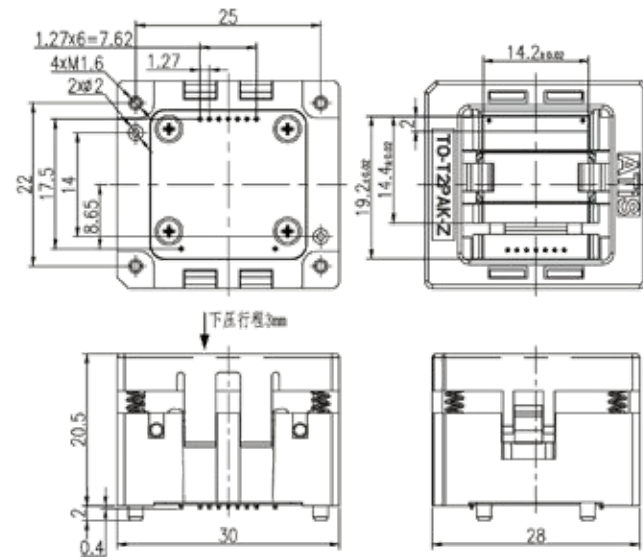
TO TRANSISTOR OUTLINE

TO-T2PAK-Z

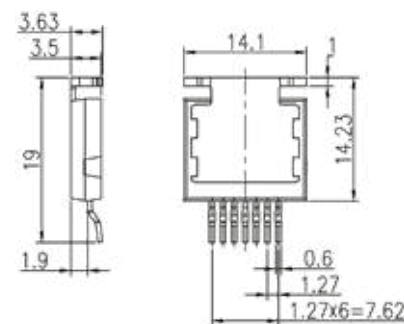


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: pogopin
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



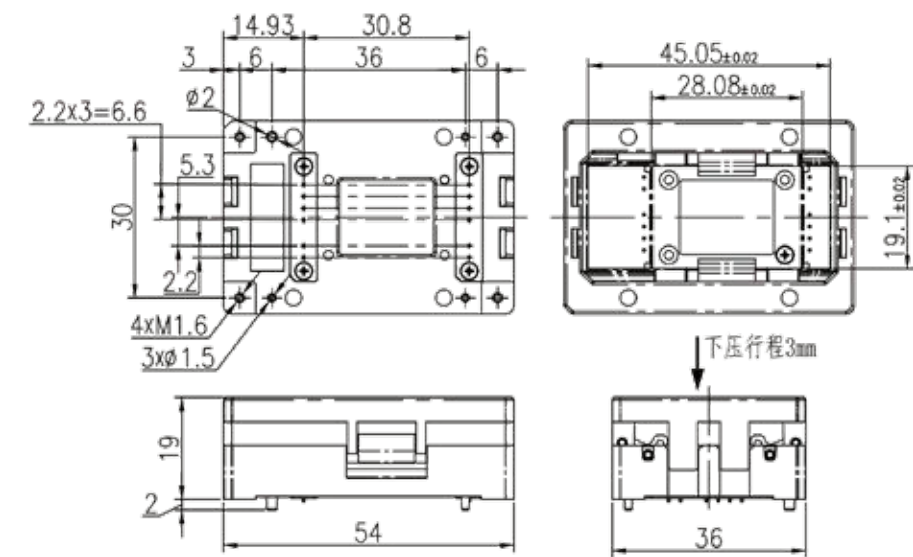
TO TRANSISTOR OUTLINE

TO-TPAK-Z

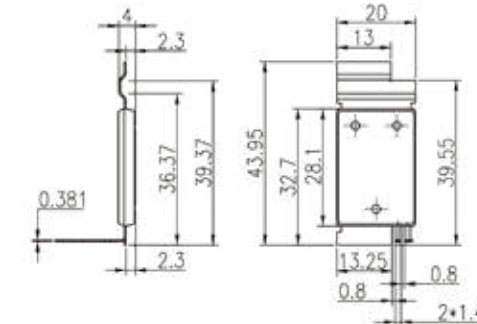


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: pogopin
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

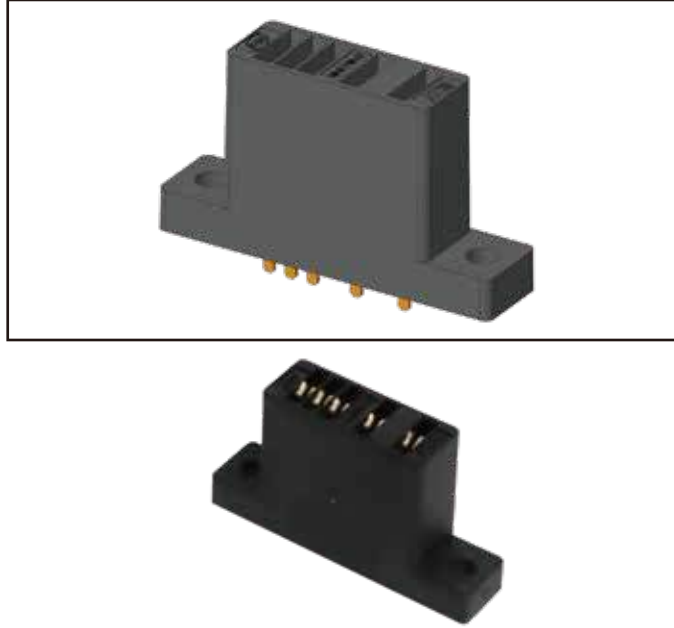


器件封装要求含/Device Packaging Requirements Including



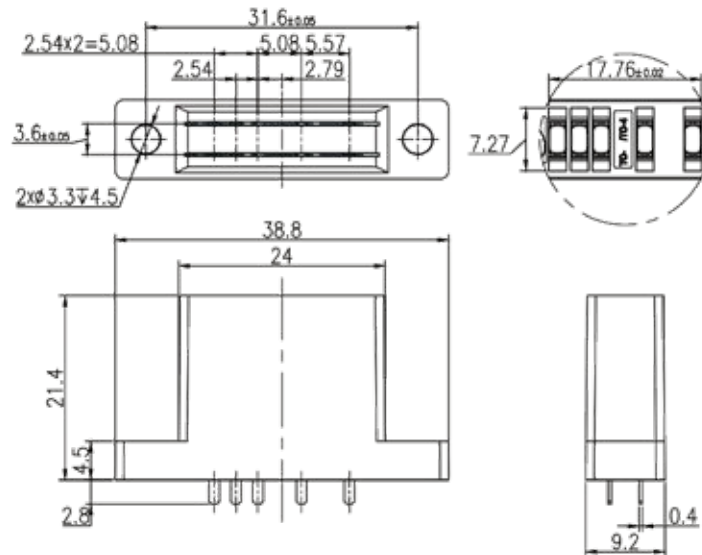
TO TRANSISTOR OUTLINE

TO-3P-TO-4P

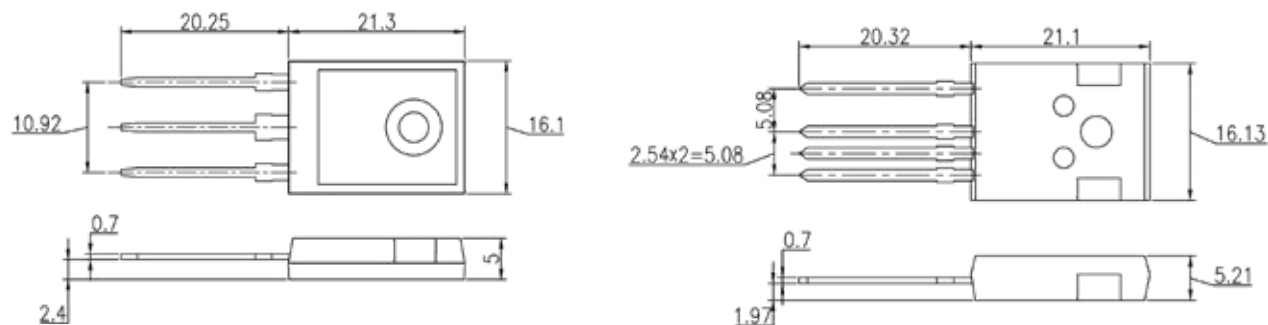


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 10A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

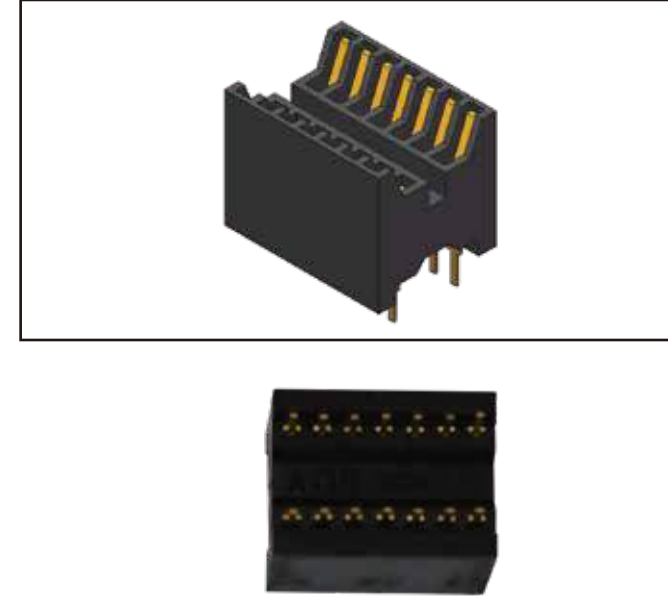


器件封装要求含/Device Packaging Requirements Including



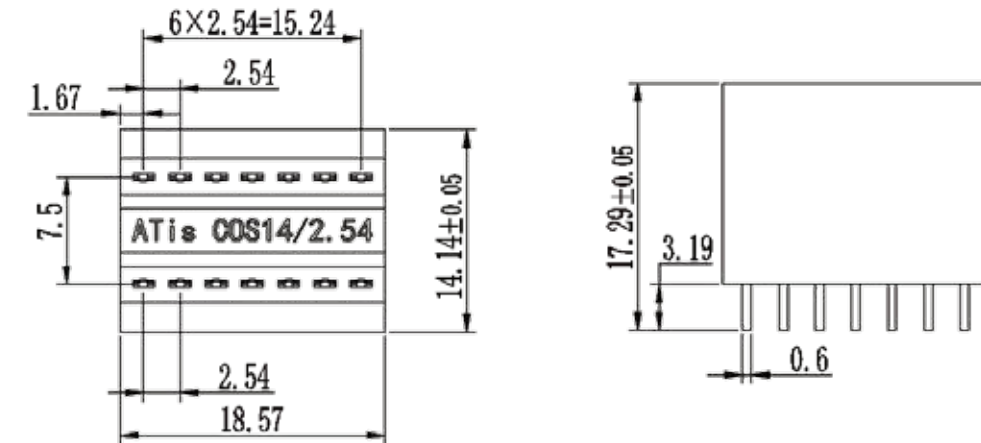
DIP CHIP ON SUBSTRATE

DIP-14-2.54

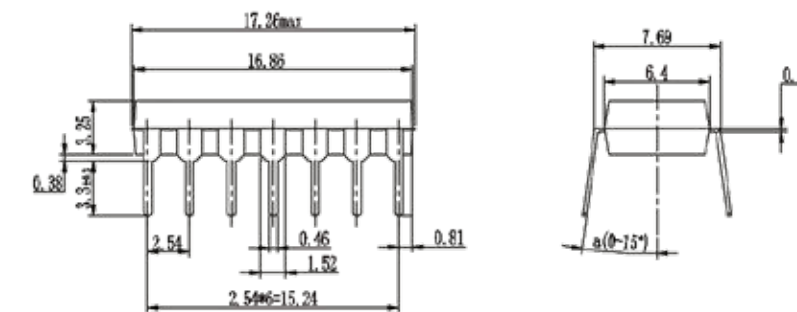


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

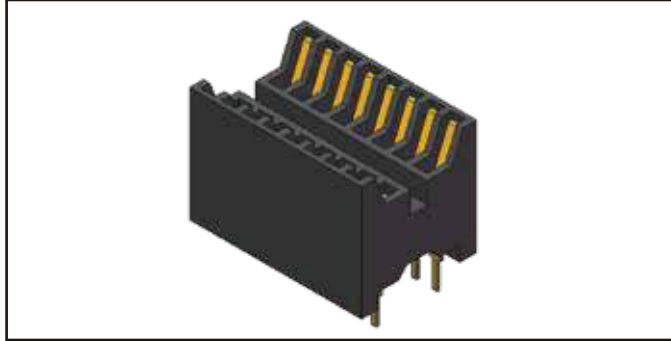


器件封装要求含/Device Packaging Requirements Including



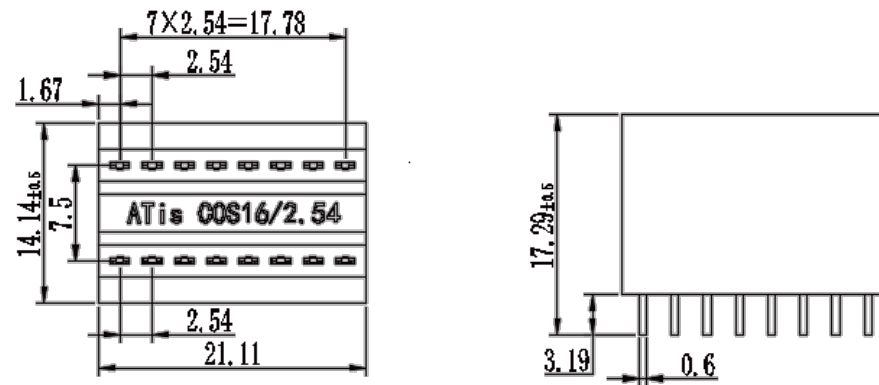
DIP CHIP ON SUBSTRATE

DIP-16-2.54

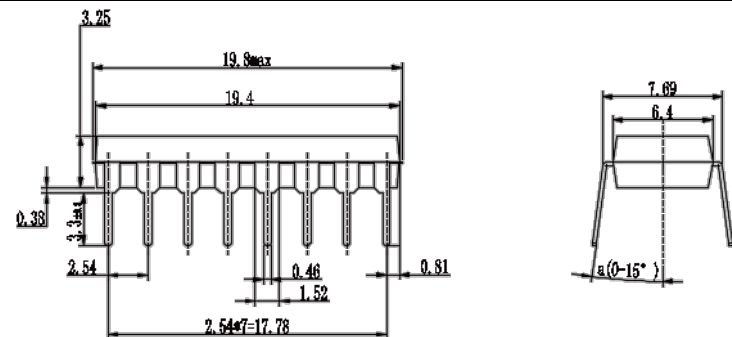


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

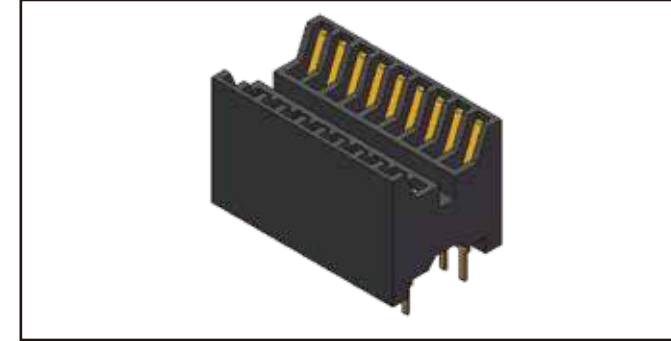


器件封装要求含/Device Packaging Requirements Including



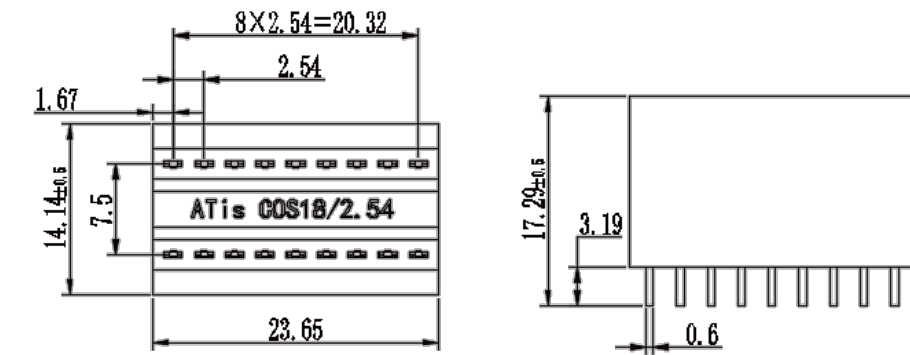
DIP CHIP ON SUBSTRATE

DIP-18-2.54

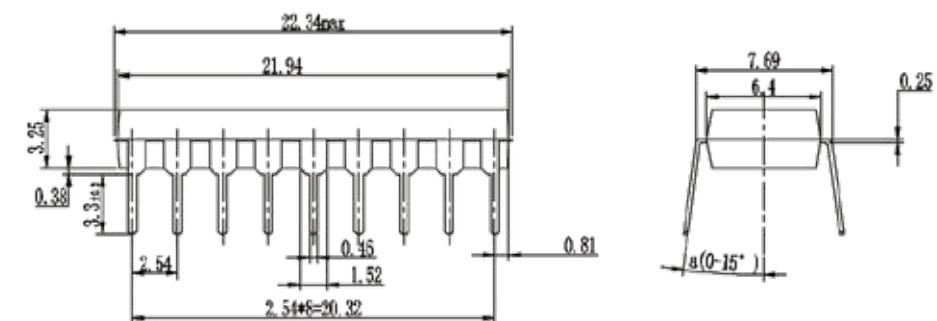


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

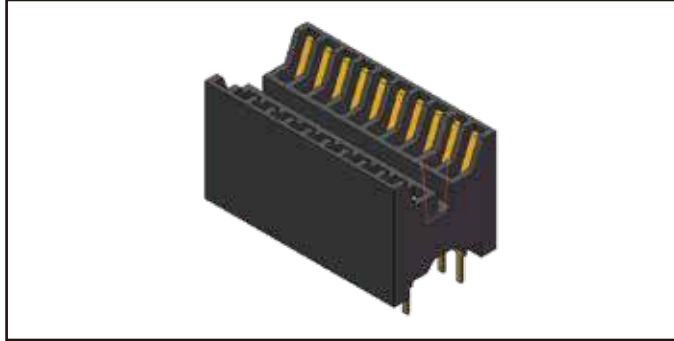


器件封装要求含/Device Packaging Requirements Including



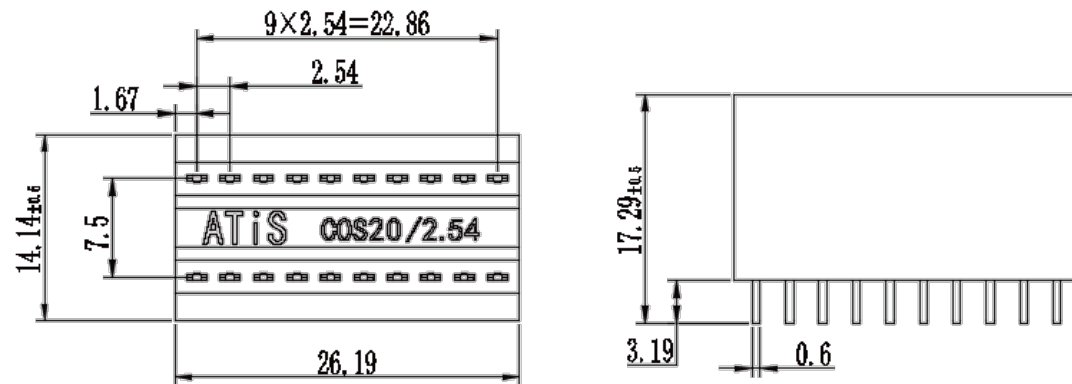
DIP CHIP ON SUBSTRATE

DIP-20-2.54

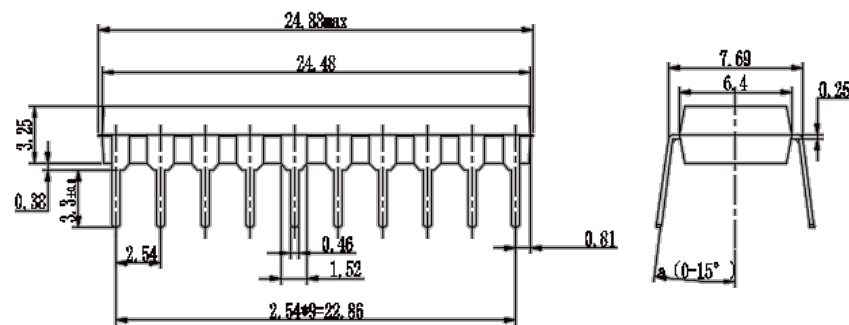


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

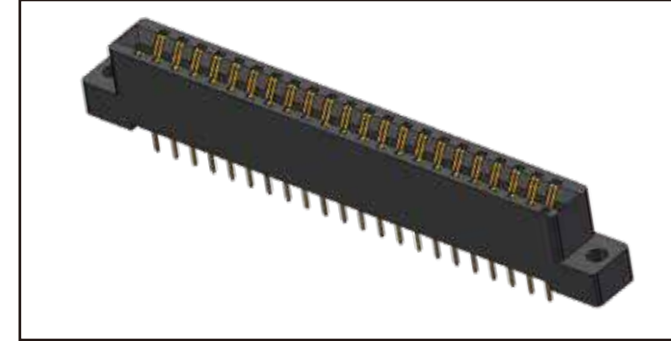


器件封装要求含/Device Packaging Requirements Including



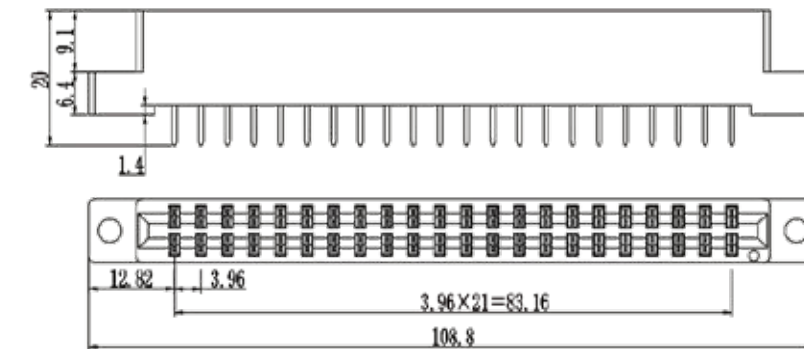
COS CHIP ON SUBSTRATE

COS-22-3.96-01

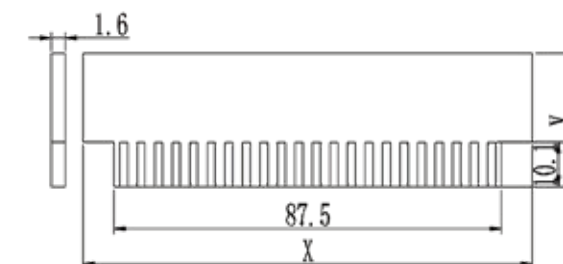


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



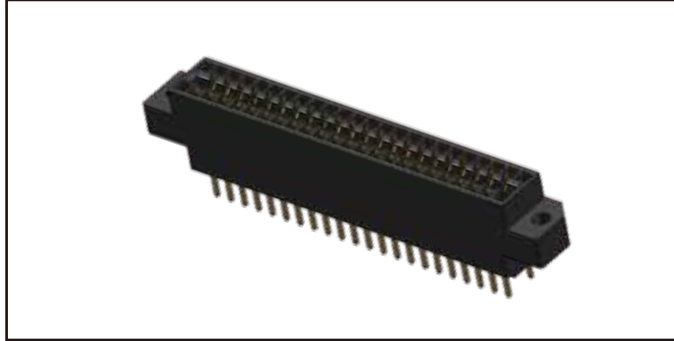
器件封装要求含/Device Packaging Requirements Including



COS

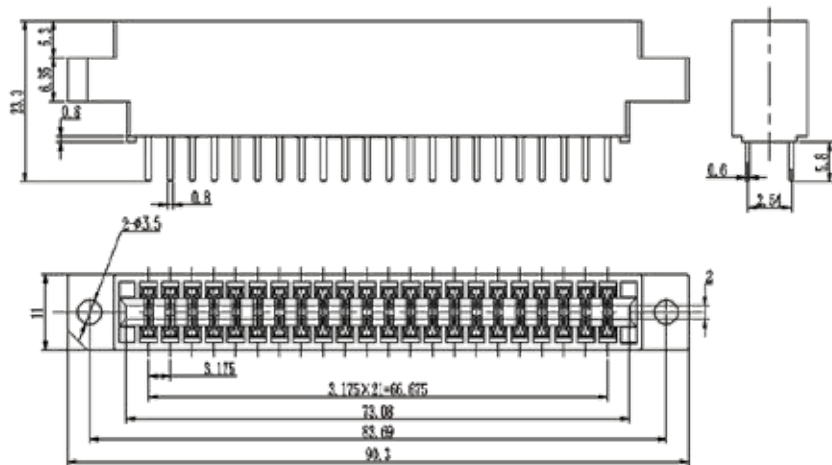
CHIP ON SUBSTRATE

COS-22-3.175

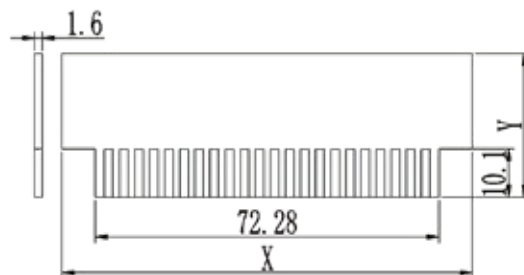


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



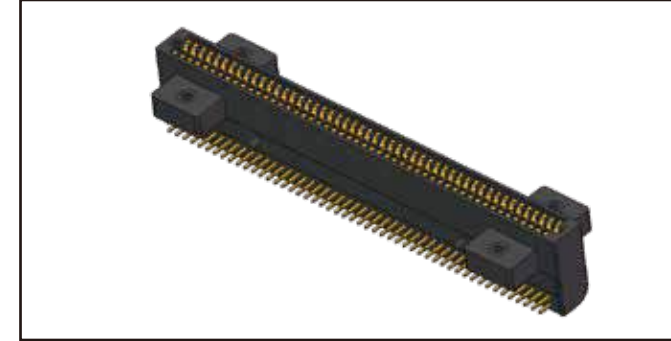
器件封装要求含/Device Packaging Requirements Including



COS

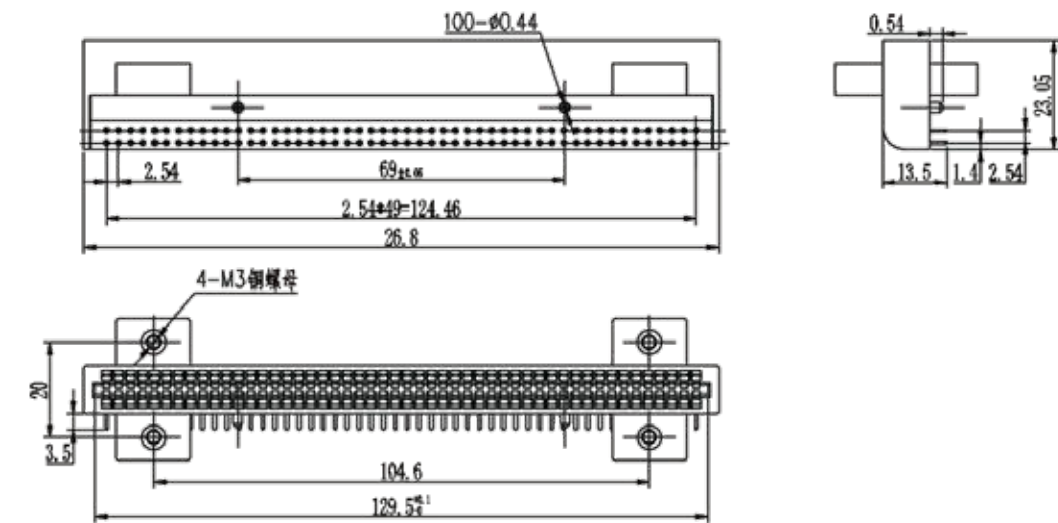
CHIP ON SUBSTRATE

COS-50-2.54-B1-01

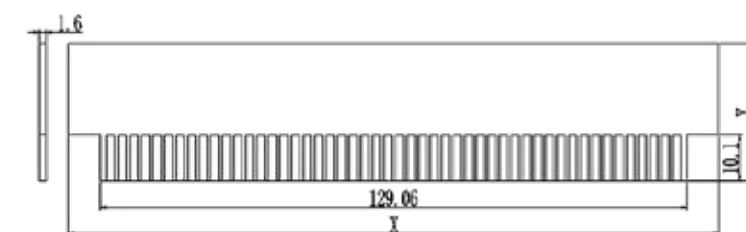


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 3A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



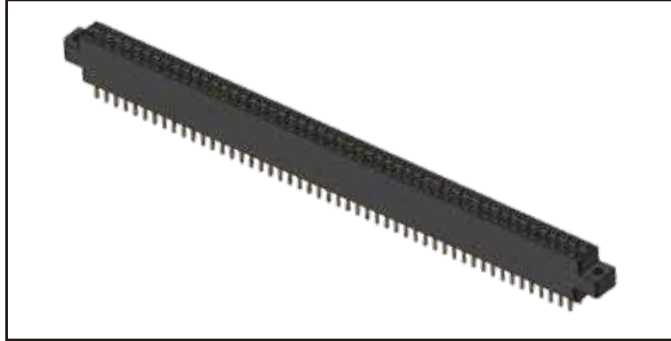
器件封装要求含/Device Packaging Requirements Including



COS

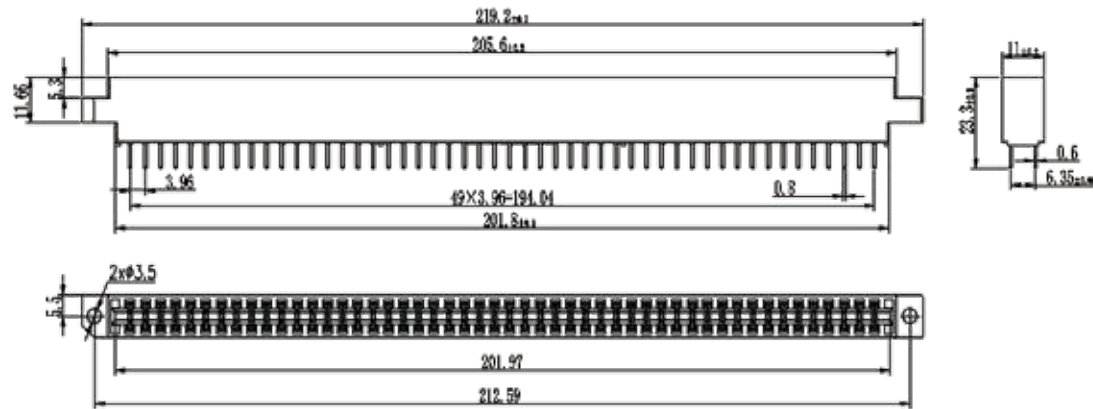
CHIP ON SUBSTRATE

COS-50-3.96

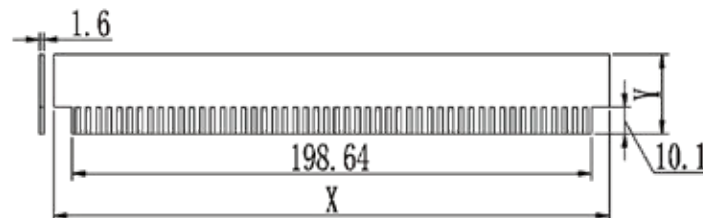


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 2A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



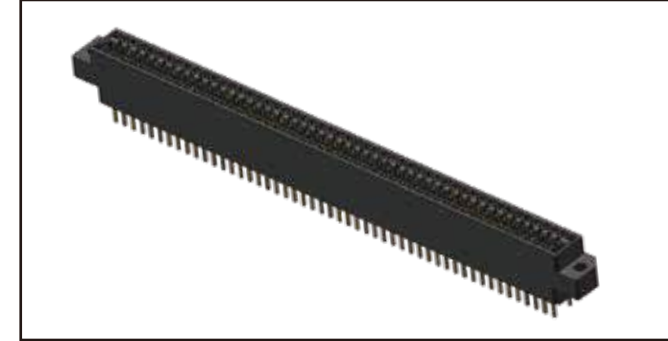
器件封装要求含/Device Packaging Requirements Including



COS

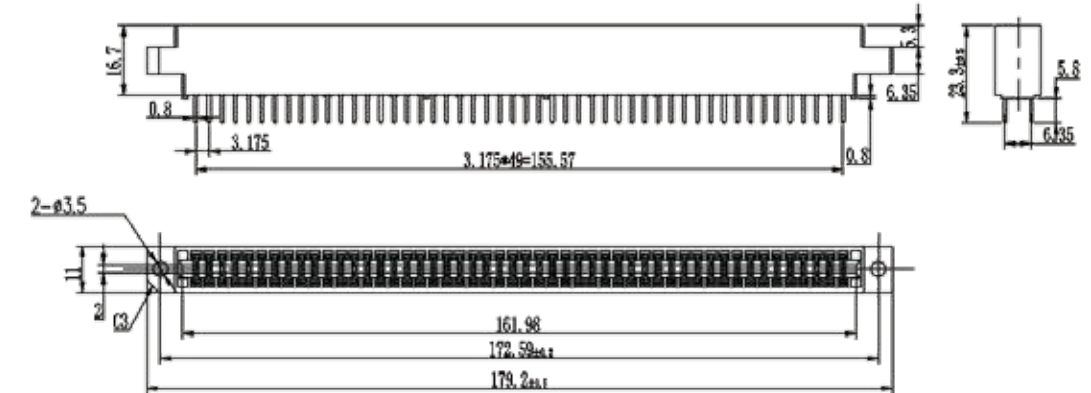
CHIP ON SUBSTRATE

COS-50-3.175-01

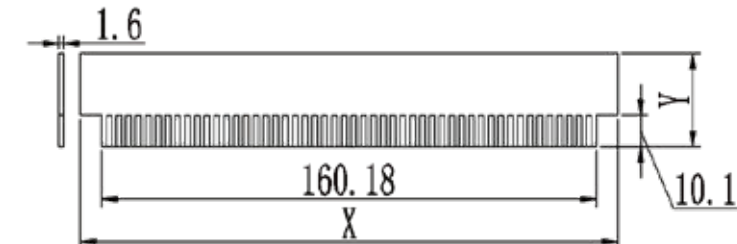


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 2A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

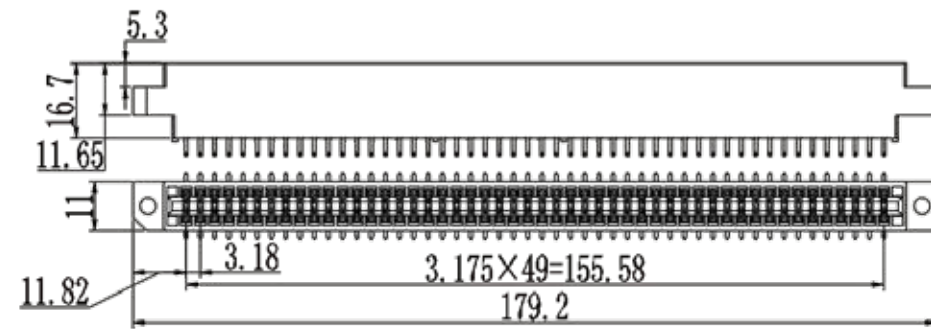


COS-50-3.175-B1-01

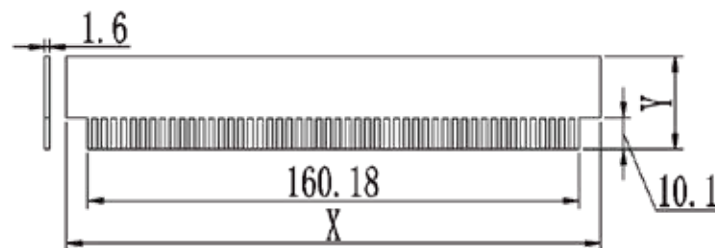


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 2A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

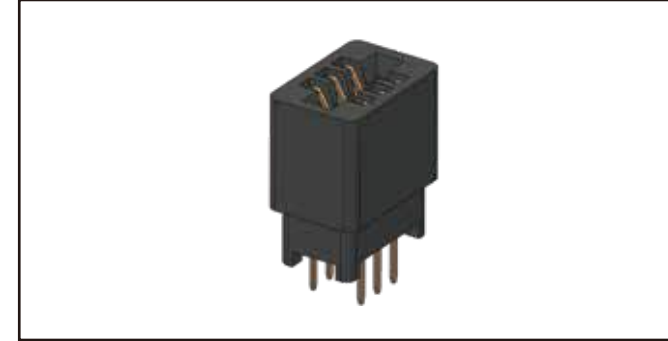
产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

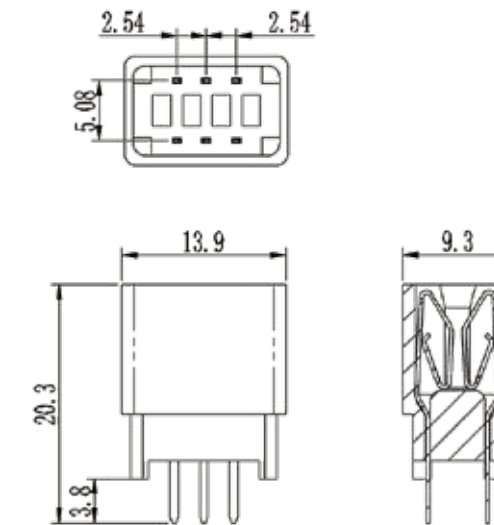


COS3-2.54

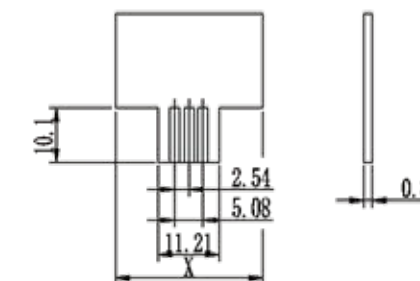


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



TQFP

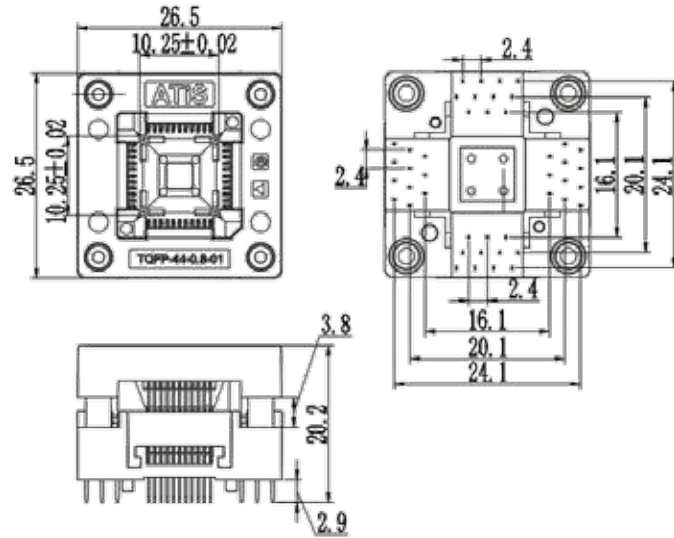
THIN QUAD FLAT PACKAGE

TQFP-44-0.8-01

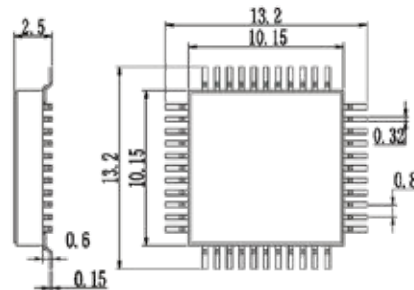


- 材质/Material
主体/Body: PEI+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



TQFP

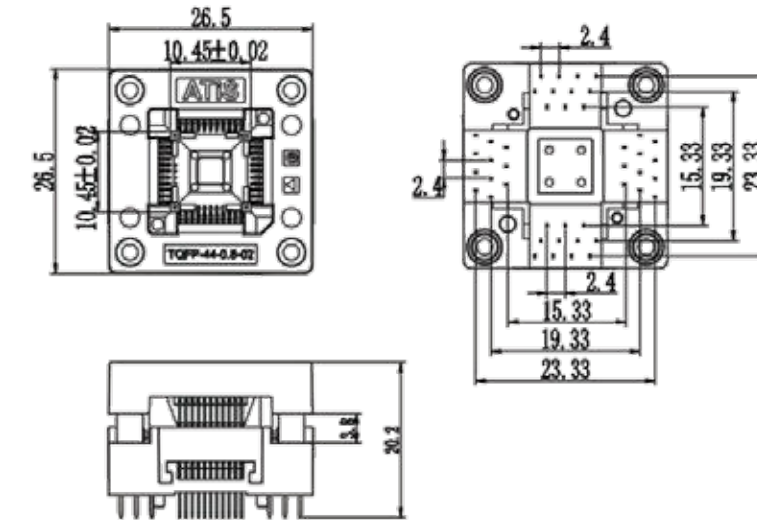
THIN QUAD FLAT PACKAGE

TQFP-44-0.8-02

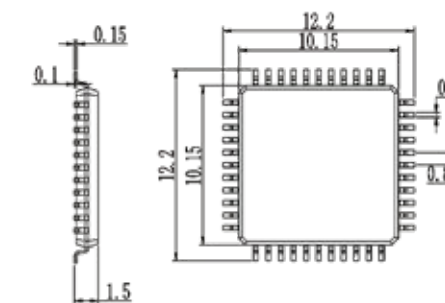


- 材质/Material
主体/Body: PEI+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



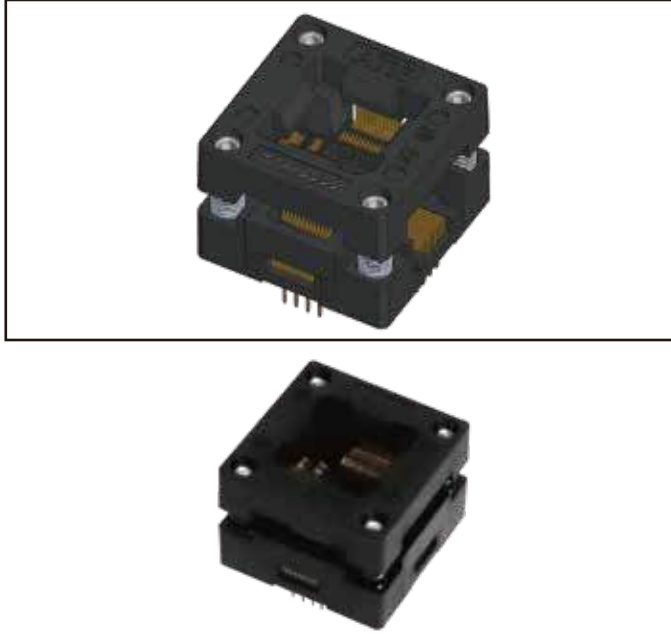
器件封装要求含/Device Packaging Requirements Including



TQFP

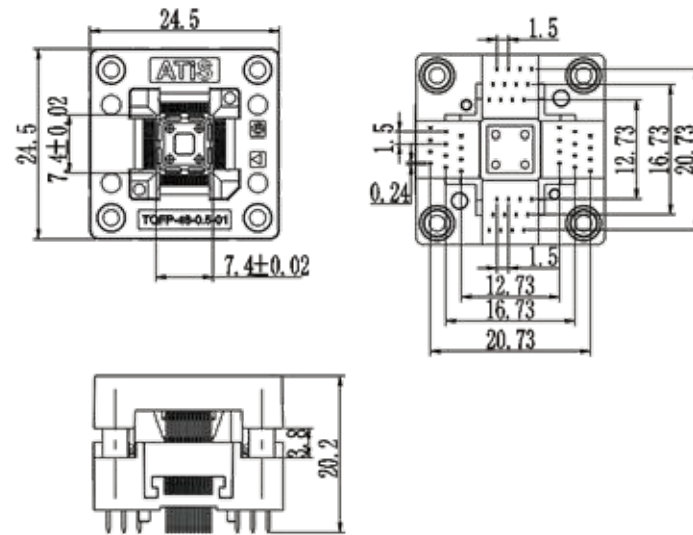
THIN QUAD FLAT PACKAGE

TQFP-48-0.5-01

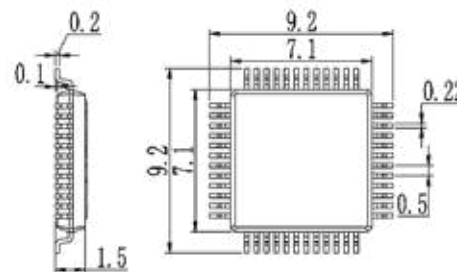


- 材质/Material
主体/Body: PEI+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



TQFP

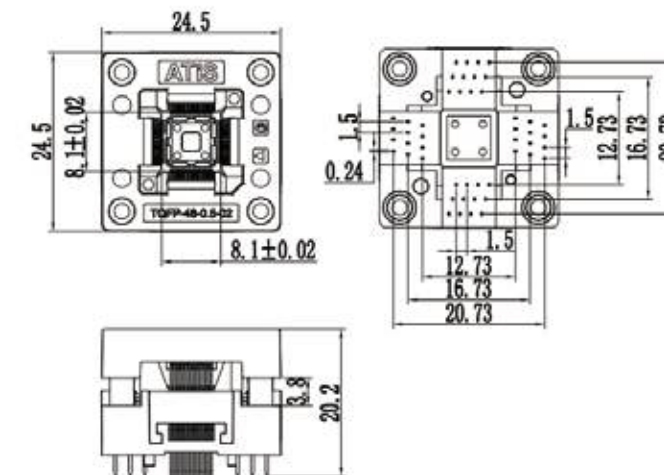
THIN QUAD FLAT PACKAGE

TQFP-48-0.5-02

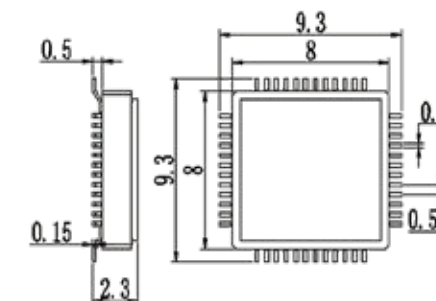


- 材质/Material
主体/Body: PEI+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



TQFP

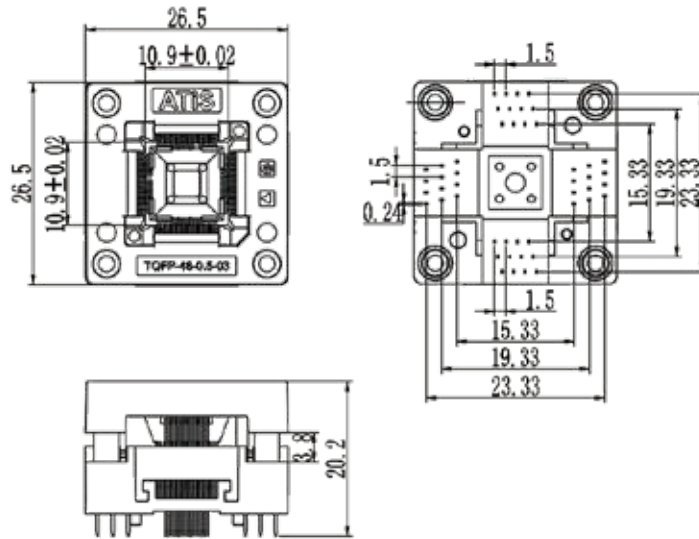
THIN QUAD FLAT PACKAGE

TQFP-48-0.5-03

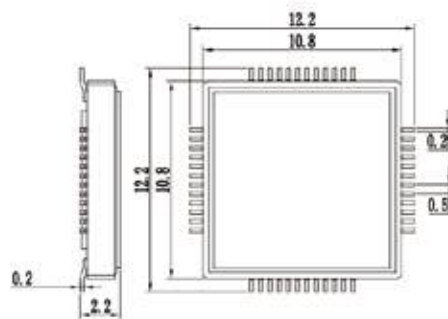


- 材质/Material
主体/Body: PEI+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



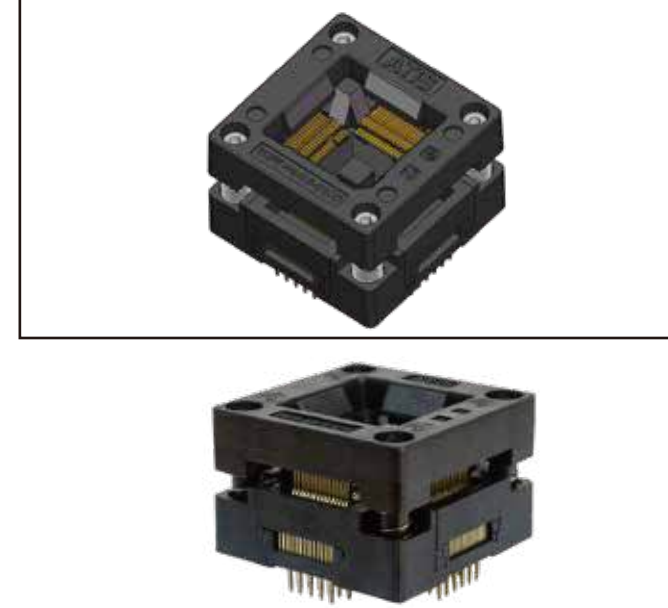
器件封装要求含/Device Packaging Requirements Including



TQFP

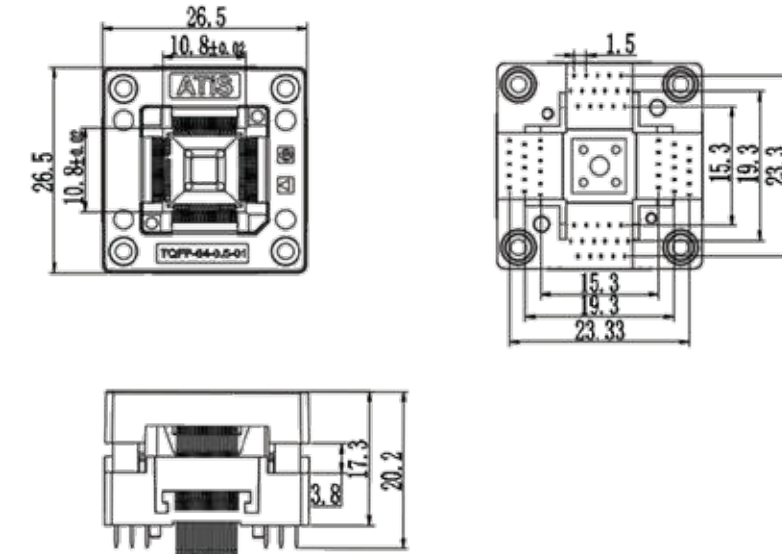
THIN QUAD FLAT PACKAGE

TQFP-64-0.5-01

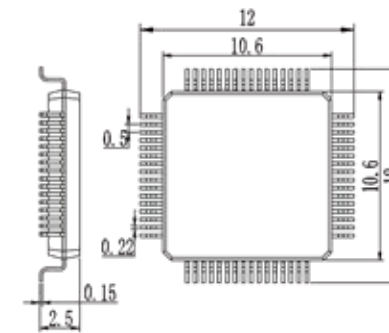


- 材质/Material
主体/Body: PEI+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



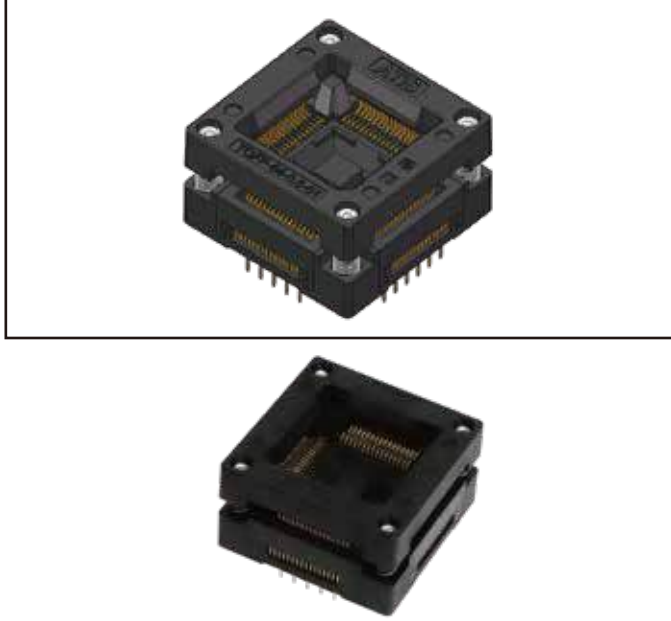
器件封装要求含/Device Packaging Requirements Including



TQFP

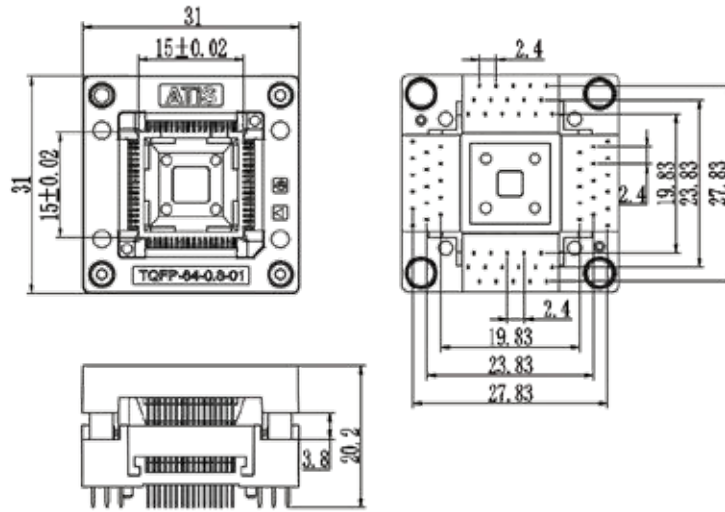
THIN QUAD FLAT PACKAGE

TQFP-64-0.8-01

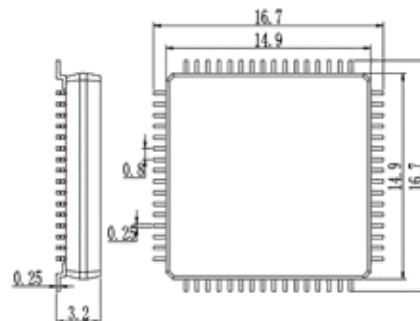


- 材质/Material
主体/Body: PEI+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



TQFP

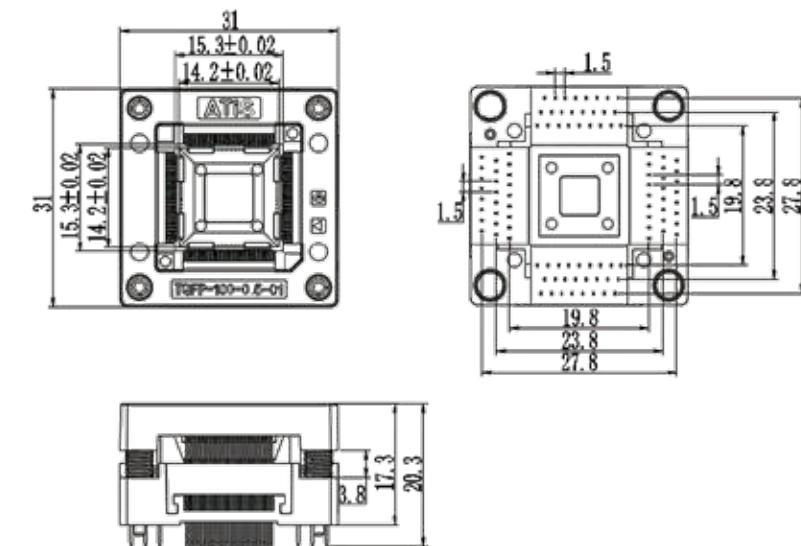
THIN QUAD FLAT PACKAGE

TQFP-100-0.5-01

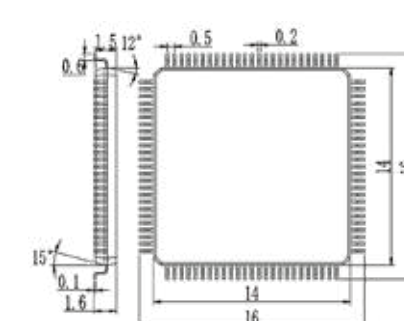


- 材质/Material
主体/Body: PEI+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



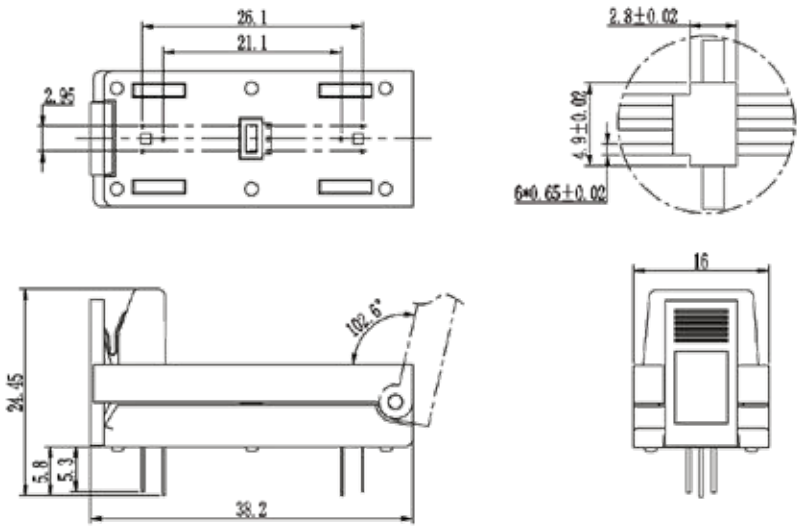
SOT
SMALL
OUTLINE
TRANSISTOR

SOT-89-6L

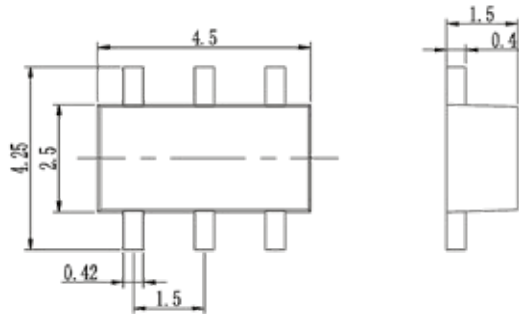


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 3A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



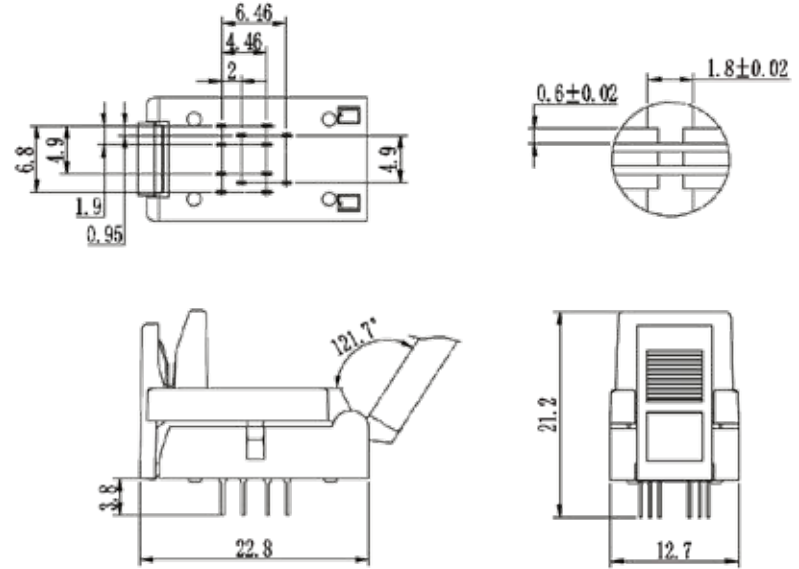
SOT
SMALL
OUTLINE
TRANSISTOR

SOT-2361

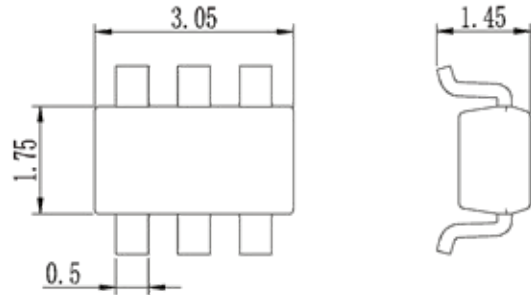


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



MCT

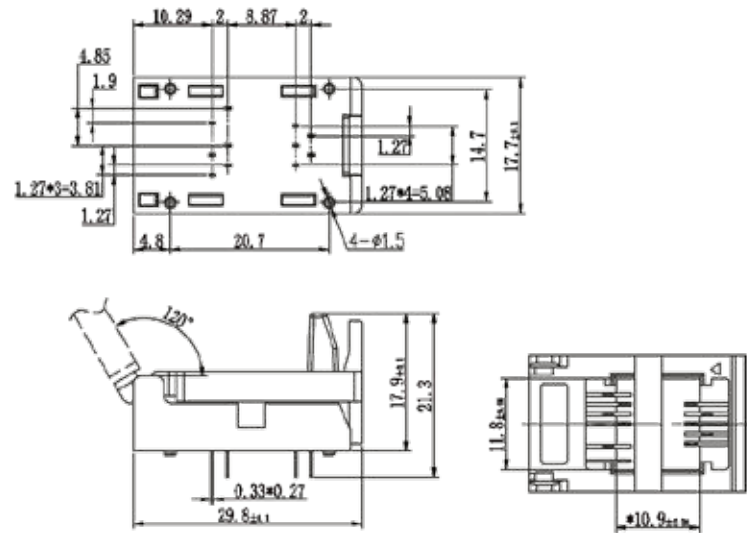
MOS CONTROLLED THYRISTOR

MCT-3600V-M

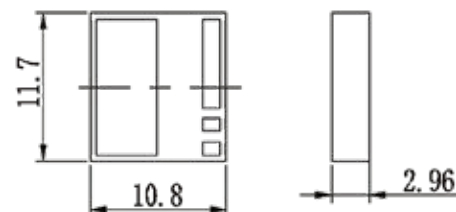


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



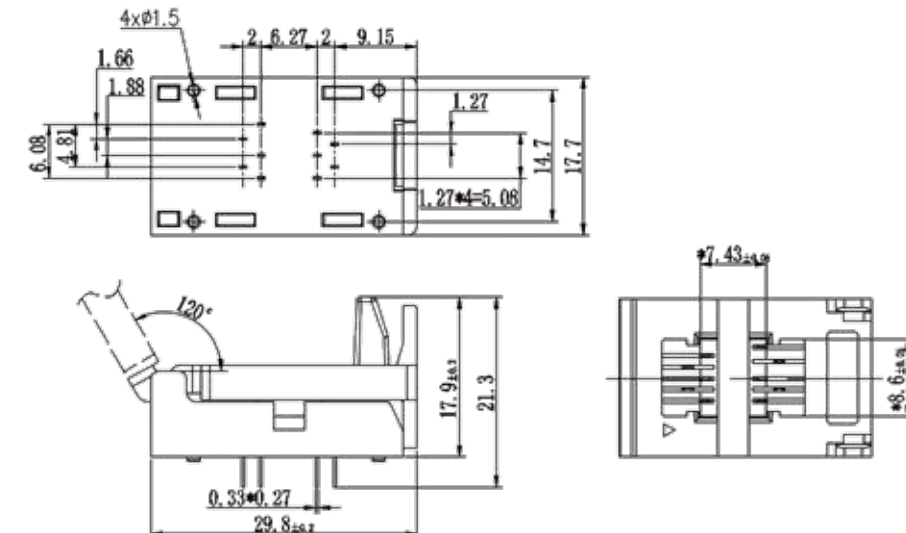
MCT MOS CONTROLLED THYRISTOR

MCT-3600V-S

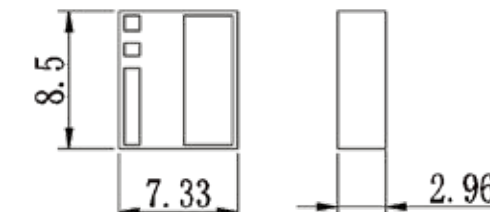


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



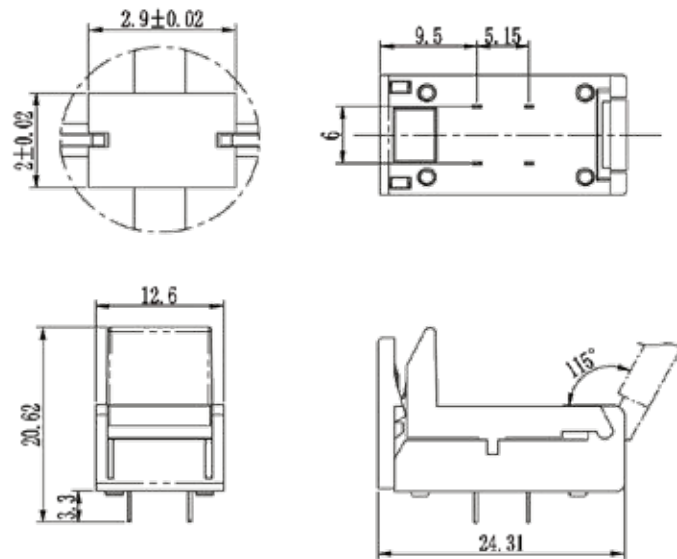
SOD SMALL OUTLINE DIODE

SOD-123

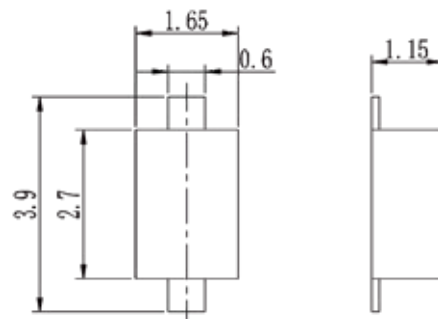


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



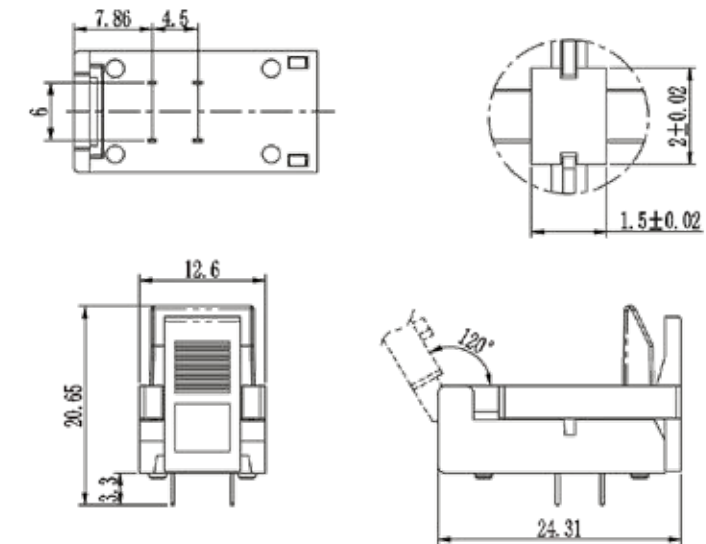
SOD SMALL OUTLINE DIODE

SOD-323

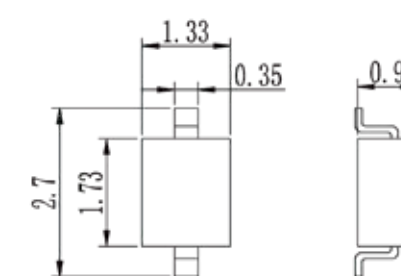


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55°C~+175°C
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



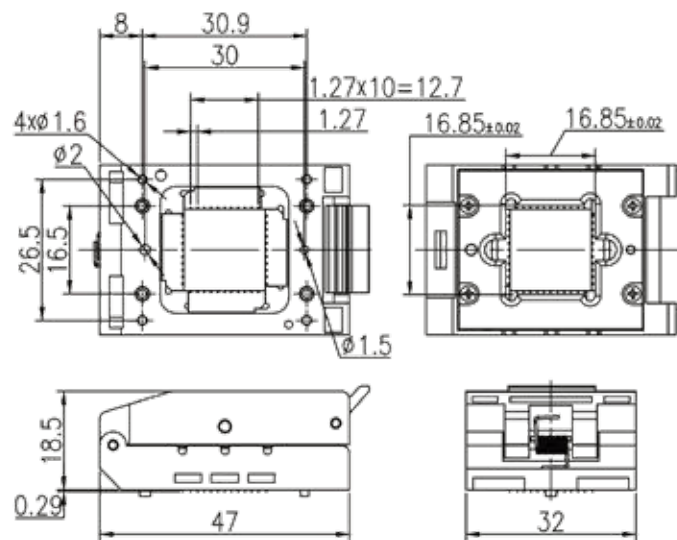
CERAMIC LEADED CHIP CARRIER

CLCC44-1.27-01

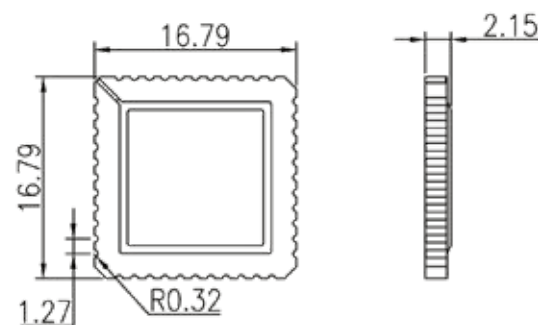


- 材质/Material
主体/Body: PPS+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including



PGA

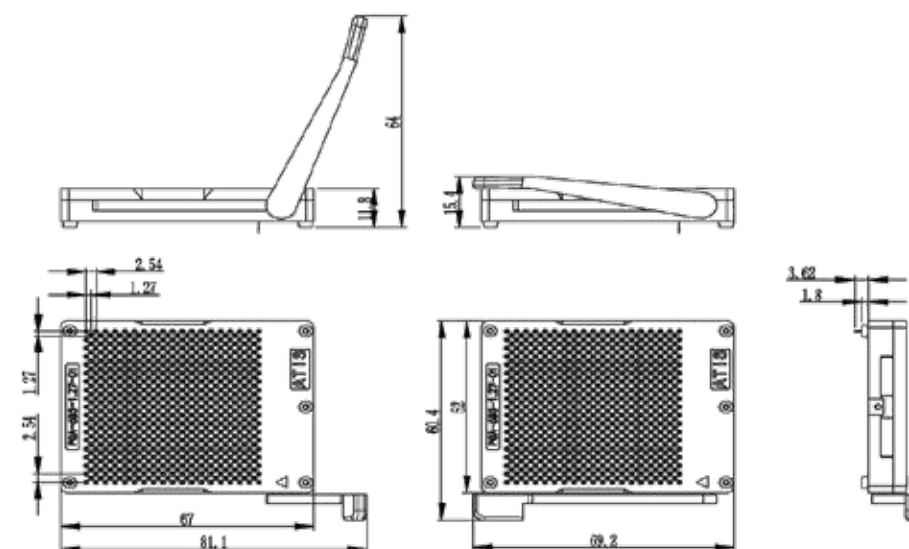
PIN GRID ARRAY

PGA-685-1.27-01



- 材质/Material
主体/Body: PEI+gf30 (Black)
接触/Contact: BeCu
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics
额定电流/Rated Current: 1A
绝缘电阻/Insulation Resistance: 1000mΩ min. at 500V DC
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others
使用温度/Operating Temperature Range: -55℃~+175℃
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

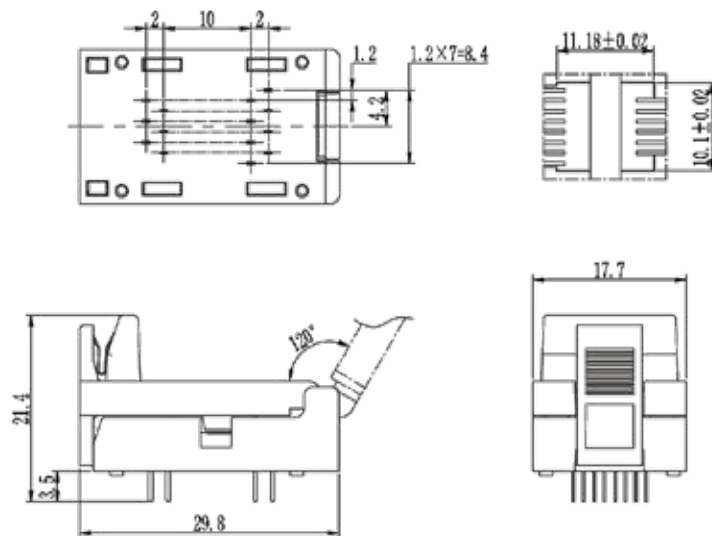
产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

The top view shows the connector with its lid closed, highlighting the 100-pin interface and the integrated microcontroller. The side view shows the connector with its lid open, revealing the internal components and the 100-pin interface. The front view shows the connector with its lid open, highlighting the 100-pin interface and the integrated microcontroller.

- 产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)

[illegible]

精密
儀器